32-bit Microcontroller

CMOS

FR60 MB91460N Series

MB91F463NA/F463NC/V460A

■ DESCRIPTION

MB91F463NA is a line of the general-purpose 32-bit RISC microcontrollers designed for embedded control applications which require high-speed real-time processing, such as consumer devices and on-board vehicle systems. MB91F463NA uses the FR60 CPU which is compatible with the FR* CPUs.

MB91F463NA contains the LIN-USART and CAN controllers.

*: FR, the abbreviation of FUJITSU RISC controller, is a line of products of Fujitsu Microelectronics Limited.

Note: MB91F463NC improved the features of MB91F463NA and updated the sector map for the flash memory. Please select MB91F463NC for the future development.

■ FEATURES

• FR60 CPU

- 32-bit RISC, load/store architecture, five-stage pipeline
- Maximum operating frequency: 80 MHz (oscillator frequency: 4 MHz; oscillator frequency multiplier: 20 (PLL clock multiplication method))
- 16-bit fixed-length instructions (basic instructions)
- Instruction execution speed: 1 instruction per cycle
- Instructions including memory-to-memory transfer, bit manipulation instructions, and barrel shift instructions: Instructions suitable for embedded applications
- Function entry/exit instructions and register data multi load store instructions: Instructions supporting C language
- Register interlock function: Facilitating assembly-language coding

(Continued)

For the information for microcontroller supports, see the following web site.

This web site includes the **"Customer Design Review Supplement"** which provides the latest cautions on system development and the minimal requirements to be checked to prevent problems before the system development.

http://edevice.fujitsu.com/micom/en-support/



• Built-in multiplier with instruction-level support

Signed 32-bit multiplication: 5 cycles Signed 16-bit multiplication: 3 cycles

- Interrupt (PC/PS saving): 6 cycles (16 priority levels)
- Harvard architecture allowing program access and data access to be executed simultaneously
- Instructions compatible with the FR family
- Internal peripheral resources
 - Flash memory capacity: 288 Kbytes
 - Internal RAM capacity: 8 Kbytes (Data RAM) + 2 Kbytes (Instruction/data RAM)
 - General-purpose port: Maximum 48 ports
 - DMAC (DMA Controller)

Maximum of 5 channels for able to operate simultaneously

2 transfer sources (internal peripheral/software)

Activation source can be selected by programs

Addressing mode specifies full 32-bit addresses (increment/decrement/fixed)

Transfer mode (burst transfer/step transfer/block transfer)

Transfer data size selectable from 8/16/32-bit

Multi-byte transfer capable (by programs)

DMAC descriptor in I/O areas (200_H to 240_H, 1000_H to 1024_H)

A/D converter (sequential comparison)

10-bit resolution: 8 channels

Conversion time: 1 µs (using at 5 V), 3 µs (using at 3.3 V)

- External interrupt inputs: 10 channels
- Bit search module (for REALOS)

Function to search from the MSB (most significant bit) for the position of the first "0", "1" or changed bit in a word

• LIN-USART (full duplex double buffer): 4 channels

Clock synchronous/asynchronous selectable

Sync-break detection

Internal dedicated baud rate generator

• I²C bus interface (Supports 400 kbps): 2 channels

Master/slave transmission and reception

Arbitration function, clock synchronization function

• CAN controller (C-CAN): 2 channels

Maximum transfer speed: 1 Mbps

32 transmission/reception message buffers

- 16-bit PPG timer: 8 channels
- 16-bit reload timer: 4 channels + 1 channel (exclusive A/D converter)
- 16-bit free-run timer: 4 channels
- Input capture: 4 channels
- Output compare: 4 channels
- 8/16-bit up/down counter: 2 channels (8-bit)/1channel (16-bit)
- · Watchdog timer
- Real-time clock
- Low-power consumption mode: Sleep/stop mode function

- Package: LQFP-64 (FPT-64P-M23)
- CMOS 0.18 μm technology
- 3.3 V only power supplies or 5 V only power supplies
- Operating temperature range: -40% to +85% (using at 5 V) -40% to +105% (using at 3.3 V)

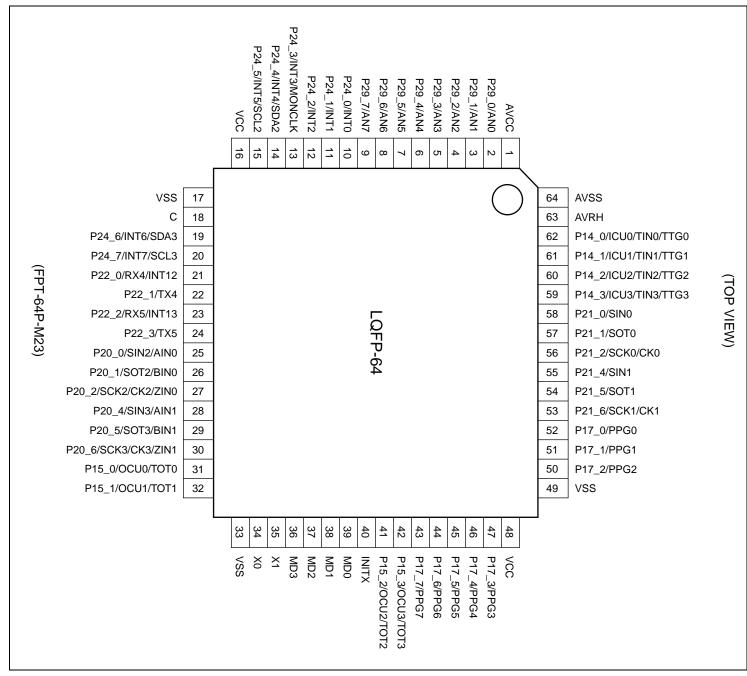
■ PRODUCT LINEUP

Part number Parameter	MB91V460A	MB91F463NA MB91F463NC			
Max core frequency (CLKB)	80 MHz				
Max resource frequency (CLKP)	40 MHz				
Max external bus frequency (CLKT)	40 MHz	_			
Max CAN frequency (CLKCAN)	20 N	ЛНz			
Technology	0.35 μm	0.18 μm			
Watchdog Timer	Yes	No			
Watchdog Timer (CR oscillator)	Yes (disengageable)	Yes			
Bit search	Ye	es			
Reset input (INITX)	Ye	es			
Hardware standby input (HSTX)	Yes	No			
Clock modulator	Yes				
Low-power mode	Yes				
DMAC	5 channels				
MAC (μDSP)	No				
MMU/MPU	MPU (16 channels)*	MPU (4 channels)*			
Flash memory	Emulation SRAM 32-bit read data	288 Kbytes			
Flash protection	_	Yes			
Data RAM	64 Kbytes	8 Kbytes			
Instruction/data RAM	64 Kbytes	2 Kbytes			
Flash-cache (instruction cache)	16 Kbytes	4 Kbytes			
Boot-ROM/BI-ROM	4 Kbytes fixed	4 Kbytes (BI-ROM)			
Real-time clock	1 chai	nnels			
Free-run timer	8 channels	4 channels			
ICU	8 channels	4 channels			
OCU	8 channels	4 channels			
16-bit reload timer	8 channels	4 channels + 1 channel			
16-bit PPG	16 channels	8 channels			

Part number Parameter	MB91V460A	MB91F463NA MB91F463NC	
16-bit PFM	1 channel	No	
Sound Generator	1 channel	No	
8/16-bit up/down counter	4 channels (8-bit) / 2 channels (16-bit)	2 channels (8-bit) / 1 channel (16-bit)	
C_CAN	6 channels (128 message buffers)	2 channels (32 message buffers)	
LIN-USART	4 channels + 4 channels (FIFO) + 8 channels	4 channels	
I ² C (400 kbps)	4 channels	2 channels	
FR external bus	Yes (32-bit address, 32-bit data)	No	
External interrupt	16 channels	10 channels	
NMI interrupts	Yes	No	
Stepping motor controller (SMC)	6 channels	No	
LCD controller (40 × 4)	1 channel	No	
10-bit A/D converter	32 channels	8 channels	
Alarm comparator	2 channels	No	
Clock supervisor	Yes	No	
Main clock oscillator	4 Mi	Hz	
Sub clock oscillator	32 kHz	_	
CR oscillator	100 kHz	100 kHz / 2 MHz	
PLL	×2	20	
DSU4	Yes	No	
EDSU	Yes (32 BP) *	Yes (8 BP)*	
Power supply voltage	3 V /	5 V	
Regulator	Ye	s	
Power consumption	n.a.	< 700 mW	
Temperature range (T _A)	0 °C to +70 °C	– 40 °C to + 105 °C	
Package	BGA-660	LQFP-64	

^{*:} MPU channels use EDSU breakpoint registers (shared operation between MPU and EDSU).

PIN ASSIGNMENT



■ PIN DESCRIPTION

Pin no.	Pin name	I/O	I/O circuit type*	Function
2 to 9	P29_0 to P29_7	I/O	В	General-purpose input/output ports
2 10 9	AN0 to AN7	1/0		Analog input pins for A/D converter
10 to 12	P24_0 to P24_2	I/O	А	General-purpose input/output ports
10 10 12	INT0 to INT2	1/0	A	External interrupt input pins
	P24_3			General-purpose input/output port
13	INT3	I/O	Α	External interrupt input pins
	MONCLK			Clock monitor output pin
	P24_4			General-purpose input/output port
14	INT4	I/O	С	External interrupt input pin
	SDA2			I ² C bus data input/output pin
	P24_5			General-purpose input/output port
15	INT5	I/O	С	External interrupt input pin
	SCL2			I ² C bus clock input/output pin
	P24_6			General-purpose input/output port
19	INT6	I/O	С	External interrupt input pin
	SDA3			I ² C bus data input/output pin
	P24_7			General-purpose input/output port
20	INT7	I/O	С	External interrupt input pin
	SCL3			I ² C bus clock input/output pin
	P22_0			General-purpose input/output port
21	RX4	I/O	Α	RX input pin of CAN4
	INT12			External interrupt input pin
22	P22_1	I/O	А	General-purpose input/output port
22	TX4	1/0	A	TX output pin of CAN4
	P22_2			General-purpose input/output port
23	RX5	I/O	Α	RX input pin of CAN5
	INT13			External interrupt input pin
24	P22_3	I/O	А	General-purpose input/output port
24	TX5	1/0	A	TX output pin of CAN5
	P20_0			General-purpose input/output port
25	SIN2	I/O	Α	Data input pin of LIN-USART2
	AIN0			Up/down counter input pin
	P20_1			General-purpose input/output port
26	SOT2	I/O	А	Data output pin of LIN-USART2
	BIN0			Up/down counter input pin

Pin no.	Pin name	I/O	I/O circuit type*	Function
	P20_2			General-purpose input/output port
27	SCK2	I/O	А	Clock input/output pin of LIN-USART2
21	CK2	1/0		Free-run timer input pin
	ZIN0			Up/down counter input pin
	P20_4			General-purpose input/output port
28	SIN3	I/O	Α	Data input pin of LIN-USART3
	AIN1			Up/down counter input pin
	P20_5			General-purpose input/output port
29	SOT3	I/O	Α	Data output pin of LIN-USART3
	BIN1			Up/down counter input pin
	P20_6			General-purpose input/output port
20	SCK3	1/0		Clock input/output pin of LIN-USART3
30	30 CK3	I/O	A	Free-run timer input pin
	ZIN1			Up/down counter input pin
	P15_0			General-purpose input/output port
31	OCU0	I/O	A	Output compare output pin
	ТОТ0			Reload timer output pin
	P15_1			General-purpose input/output port
32	OCU1	I/O	Α	Output compare output pin
-	TOT1			Reload timer output pin
34	X0	_	J	Clock (oscillation) input
35	X1	_	J	Clock (oscillation) output
36	MD3	I	I	Mode setting pin
37	MD2	I	G	Mode setting pin
38	MD1	I	G	Mode setting pin
39	MD0	I	G	Mode setting pin
40	INITX	I	Н	External reset input
	P15_2			General-purpose input/output port
41	OCU2	I/O	Α	Output compare output pin
-	TOT2			Reload timer output pin
	P15_3			General-purpose input/output port
42	OCU3	I/O	Α	Output compare output pin
	ТОТ3			Reload timer output pin
43 to 47,	P17_7 to P17_0	I/O	۸	General-purpose input/output ports
50 to 52	PPG7 to PPG0	1/0	A	PPG timer output pins

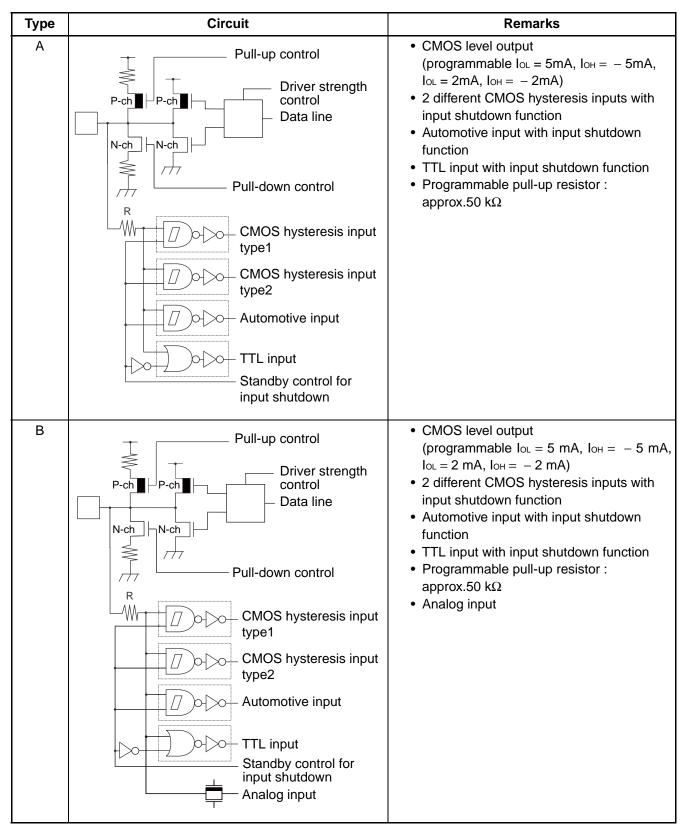
Pin no.	Pin name	1/0	I/O circuit type*	Function
	P21_6			General-purpose input/output port
53	SCK1	I/O	Α	Clock input/output pin of LIN-USART1
	CK1			Free-run timer input pin
54	P21_5	I/O	А	General-purpose input/output port
34	SOT1	1/0	A	Data output pin of LIN-USART1
55 -	P21_4	I/O	А	General-purpose input/output port
55	SIN1	1/0	A	Data input pin of LIN-USART1
	P21_2			General-purpose input/output port
56	SCK0	I/O	А	Clock input/output pin of LIN-USART0
CK0			Free-run timer input pin	
57	P21_1	I/O	А	General-purpose input/output port
57	SOT0	1/0	A	Data output pin of LIN-USART0
F0	P21_0	I/O	۸	General-purpose input/output port
58	SIN0	1/0	A	Data input pin of LIN-USART0
	P14_3			General-purpose input/output port
59	ICU3	I/O	А	Input capture input pin
59	TIN3	1/0	A	External trigger input pin of reload timer
	TTG3			PPG timer input pin
	P14_2			General-purpose input/output port
60	ICU2	I/O	А	Input capture input pin
60	TIN2	1/0	A	External trigger input pin of reload timer
	TTG2			PPG timer input pin
	P14_1			General-purpose input/output port
61	ICU1	I/O	٨	Input capture input pin
61	TIN1	1/0	A	External trigger input pin of reload timer
	TTG1			PPG timer input pin
	P14_0			General-purpose input/output port
62	ICU0	I/O	^	Input capture input pin
02	TIN0	1/0	А	External trigger input pin of reload timer
	TTG0			PPG timer input pin

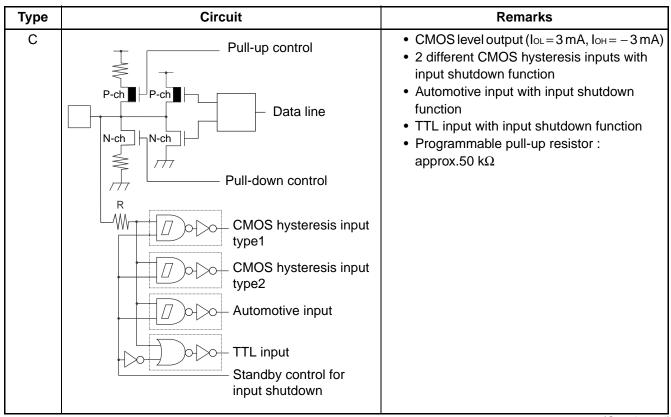
^{* :} For I/O circuit type, refer to "■ I/O CIRCUIT TYPE".

[Power supply/GND pins]

Pin no.	Pin name	I/O	Function
17, 33, 49	VSS	_	GND pins
16, 48	VCC		3.3 V/5 V power supply pins
64	AVSS		Analog GND pin for A/D converter
1	AVCC		3.3 V/5 V power supply pin for A/D converter
63	AVRH		Reference power supply pin for A/D converter
18	С	_	Capacitor connection pin for internal regulator

■ I/O CIRCUIT TYPE





Туре	Circuit	Remarks
G	R CMOS level input	MASK ROM and evaluation device: CMOS level input Flash device: CMOS level input 12 V resistant (for MD [2:0])
Н	₹ Pull-up resistor	 CMOS hysteresis input Pull-up resistor value : approx.50 kΩ
	R CMOS Hysteresis input	
I	R CMOS Hysteresis input	 CMOS hysteresis input Pull-down resistor value : approx.50 kΩ
J	X1 Xout	Oscillation circuit
	X0 Standby control signal	

■ PRECAUTIONS FOR HANDLING THE DEVICES

Any semiconductor devices have inherently a certain rate of failure. The possibility of failure is greatly affected by the conditions in which they are used (circuit conditions, environmental conditions, etc.). This page describes precautions that must be observed to minimize the chance of failure and to obtain higher reliability from your FUJITSU semiconductor devices.

1. Precautions for Product Design

This section describes precautions when designing electronic equipment using semiconductor devices.

· Absolute Maximum Ratings

Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

• Recommended Operating Conditions

The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their FUJITSU representatives beforehand.

· Processing and Protection of Pins

These precautions must be followed when handling the pins which connect semiconductor devices to power supply and input/output functions.

(1) Preventing Over-Voltage and Over-Current Conditions

Exposure to voltage or current levels in excess of maximum ratings at any pin is likely to cause deterioration within the device, and in extreme cases leads to permanent damage of the device. Try to prevent such over voltage or over-current conditions at the design stage.

(2) Protection of Output Pins

Shorting of output pins to supply pins or other output pins, or connection to large capacitance can cause large current flows. Such conditions if present for extended periods of time can damage the device. Therefore, avoid this type of connection.

(3) Handling of Unused Input Pins

Unconnected input pins with very high impedance levels can adversely affect stability of operation. Such pins should be connected through an appropriate resistance to a power supply pin or ground pin.

• Latch-up

Semiconductor devices are constructed by the formation of P-type and N-type areas on a substrate. When subjected to abnormally high voltages, internal parasitic PNPN junctions (called thyristor structures) may be formed, causing large current levels in excess of several hundred mA to flow continuously at the power supply pin. This condition is called latch-up.

Note: The occurrence of latch-up not only causes loss of reliability in the semiconductor device, but can cause injury or damage from high heat, smoke or flame. To prevent this from happening, do the following:

- (a) Be sure that voltages applied to pins do not exceed the absolute maximum ratings. This should include attention to abnormal noise, surge levels, etc.
- (b) Be sure that abnormal current flows do not occur during the power-on sequence.

• Observance of Safety Regulations and Standards

Most countries in the world have established standards and regulations regarding safety, protection from electromagnetic interference, etc. Customers are requested to observe applicable regulations and standards in the design of products.

· Fail-Safe Design

Any semiconductor devices have inherently a certain rate of failure. You must protect against injury, damage or loss from such failures by incorporating safety design measures into your facility and equipment such as redundancy, fire protection, and prevention of over-current levels and other abnormal operating conditions.

Precautions Related to Usage of Devices

FUJITSU semiconductor devices are intended for use in standard applications (computers, office automation and other office equipment, industrial, communications, and measurement equipment, personal or household devices, etc.).

CAUTION: Customers considering the use of our products in special applications where failure or abnormal operation may directly affect human lives or cause physical injury or property damage, or where extremely high levels of reliability are demanded (such as aerospace systems, atomic energy controls, submarine repeaters, vehicle operating controls, medical devices for life support, etc.) are requested to consult with FUJITSU sales representatives before such use. The company will not be responsible for damages arising from such use without prior approval.

2. Precautions for Package Mounting

Package mounting may be either lead insertion type or surface mounting type. In either case, quality assurance of heat resistance are applied for mounting under the Fujitsu's recommended conditions only at the soldering stage. For detailed information on mount conditions, contact the sales representative.

· Lead Insertion Type

Mounting of lead insertion type packages onto printed circuit boards may be done by two methods: direct soldering on the board, or mounting by using a socket.

Direct mounting onto boards normally involves processes for inserting leads into through-holes on the board and using the flow soldering (wave soldering) method of applying liquid solder.

In this case, the soldering process usually causes leads to be subjected to thermal stress in excess of the absolute ratings for storage temperature. Mounting processes should conform to FUJITSU recommended mounting conditions.

If socket mounting is used, differences in surface treatment of the socket contacts and IC lead surfaces can lead to contact deterioration after long periods. For this reason it is recommended that the surface treatment of socket contacts and IC leads be verified before mounting.

Surface Mount Type

Surface mount packaging has longer and thinner leads than lead-insertion packaging, and therefore leads are more easily deformed or bent. The use of packages with higher pin counts and narrower pin pitch results in increased susceptibility to open connections caused by deformed pins, or shorting due to solder bridges. You must use appropriate mounting techniques. FUJITSU recommends the solder reflow method, and has established a ranking of mounting conditions for each product. Users are advised to mount packages in accordance with FUJITSU ranking of recommended conditions.

Storage of Semiconductor Devices

Because plastic chip packages are formed from plastic resins, exposure to natural environmental conditions will cause absorption of moisture. During mounting, the application of heat to a package that has absorbed moisture can cause surfaces to peel, reducing moisture resistance and causing packages to crack. To prevent, do the following:

- (a) Avoid exposure to rapid temperature changes, which cause moisture to condense inside the product. Store products in locations where temperature changes are slight.
- (b) Use dry boxes for product storage. Products should be stored below 70% relative humidity, and at temperatures between +5 °C to +30 °C.
- (c) When necessary, FUJITSU packages semiconductor devices in highly moisture-resistant aluminum laminate bags, with a silica gel desiccant. Devices should be sealed in their aluminum laminate bags for storage.
- (d) Avoid storing packages where they are exposed to corrosive gases or high levels of dust.

Baking

Packages that have absorbed moisture may be de-moisturized by baking (heat drying). Follow the FUJITSU recommended conditions for baking.

· Static Electricity

Because semiconductor devices are particularly susceptible to damage by static electricity, you must take the following precautions:

- (a) Maintain relative humidity in the working environment between 40% and 70%. Use of an apparatus for ion generation may be needed to remove electricity.
- (b) Electrically ground all conveyors, solder vessels, soldering irons and peripheral equipment.
- (c) Eliminate static body electricity by the use of rings or bracelets connected to ground through high resistance (on the level of 1 $M\Omega$). Wearing of conductive clothing and shoes, use of conductive floor mats and other measures to minimize shock loads is recommended.
- (d) Ground all fixtures and instruments, or protect with anti-static measures.
- (e) Avoid the use of styrofoam or other highly static-prone materials for storage of completed board assemblies.

3. Precautions for Use Environment

Reliability of semiconductor devices depends on ambient temperature and other conditions as described above. For reliable performance, do the following:

- (1) Humidity
 - Prolonged use in high humidity can lead to leakage in devices as well as printed circuit boards. If high humidity levels are anticipated, consider anti-humidity processing.
- (2) Discharge of Static Electricity

 When high-voltage charges exist close to semiconductor devices, discharges can cause abnormal operation.

 In such cases, use anti-static measures or processing to prevent discharges.
- (3) Corrosive Gases, Dust, or Oil

 Exposure to corrosive gases or contact with dust or oil may lead to chemical reactions that will adversely affect the device. If you use devices in such conditions, consider ways to prevent such exposure or to protect the devices.
- (4) Radiation, Including Cosmic Radiation

 Most devices are not designed for environments involving exposure to radiation or cosmic radiation. Users should provide shielding as appropriate.
- (5) Smoke, Flame

Note: Plastic molded devices are flammable, and therefore should not be used near combustible substances. If devices begin to smoke or burn, there is danger of the release of toxic gases.

Customers considering the use of FUJITSU products in other special environmental conditions should consult with FUJITSU sales representatives.

■ HANDLING DEVICES

Power supply pins

Because there are multiple VCC and VSS pins, respective pins at the same potential are interconnected to prevent malfunctions such as latch-up. However, you must connect the pins externally to the power supply and ground lines to reduce the electro-magnetic emission levels, to prevent abnormal operation of strobe signals caused by the rise in the ground level, and to conform to the total output current rating. Furthermore, the current supply source should be connected to the VCC and VSS pins of the device at a low impedance.

It is recommended to connect a ceramic bypass capacitor of approximately 0.1 μ F as a bypass capacitor between the Vcc and Vss near this device.

· Crystal oscillator circuit

Noise in proximity to the X0 and X1 pins can cause the device to malfunction. Printed circuit boards should be designed so that the X0 and X1 pins, crystal oscillator (or ceramic oscillator), and bypass capacitors connected to ground are located near the device and ground.

It is recommended that the printed circuit board artwork be designed such that the X0 and X1 pins are surrounded by ground plane for the stable operation.

Please request the oscillator manufacturer to evaluate the oscillational characteristics of the crystal and this device.

Mode pins (MD0 to MD3)

Connect them directly to VCC or VSS. To prevent the device from entering test mode accidentally due to noise, minimize the lengths of the patterns between each mode pin and VCC or VSS on the printed circuit board as much as possible and connect them at a low impedance. When used pulling down, design your circuit not to generate noises with a resistance 1 $k\Omega$ or less. Test your circuit and confirm that there is no problem.

Operation at power-on

At power-on, it is necessary to make the terminal INITX "L" level.

Maintain the "L" level input to the INITX pin for the duration of the stabilization wait time immediately after the power on to ensure the stabilization wait time as required by the oscillator circuit.

Note on oscillator input at power-on

At power-on, ensure that the clock is input until the oscillator stabilization wait time has elapsed.

· Built-in regulator

As this series includes built-in step-down regulators, always connect a bypass capacitor of 4.7 μ F or more to the C pin for use by the regulator.

Notes on power on/off

Connect/disconnect the power supply pins when power on/off, or turn on/off in the following order.

Power on : VCC \rightarrow AVCC, AVRH Power off : AVCC, AVRH \rightarrow VCC

Precautions for the STOP mode

Set 1 to the bit 0 (OSCD1) of STCR register. When shifting to the STOP mode, a regulator switches to the standby regulator (for low-consumption current).

Due to the limited drive current, stop the (programming/erasing) access to the A/D converter and Flash before shifting to the STOP mode.

Serial communication

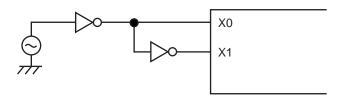
There is a possibility to receive wrong data due to the noise or other causes on the serial communication. Therefore, design a board so as to avoid noise.

Consider receiving of wrong data when designing the system. For example, apply a checksum to detect an error. If an error is detected, retransmit the data.

Notes on using external clock

When using the external clock, as a general rule you should simultaneously supply X0 and X1 pins. And also, the clock signal to X0 should be supplied a clock signal with the reverse phase to X1 pins. However, in this case the stop mode (oscillation stop mode) must not be used.

Example of using external clock (normal)



Note: Stop mode (oscillation stop mode) cannot be used.

• Notes on operating in PLL clock mode

If the oscillator is disconnected or the clock input stops when the PLL clock is selected, the microcontroller may continue to operate at the free-running frequency of the self-oscillating circuit of the PLL. However, this self-running operation cannot be guaranteed.

■ NOTES ON DEBUGGER

Execution of the RETI Command

If single-step execution is used in an environment where an interrupt occurs frequently, the corresponding interrupt handling routine will be executed repeatedly to the exclusion of other processing. This will prevent the main routine and the handlers for low priority level interrupts from being executed (For example, if the time-base timer interrupt is enabled, stepping over the RETI instruction will always break on the first line of the time-base timer interrupt handler).

Disable the corresponding interrupts when the corresponding interrupt handling routine no longer needs debugging.

Break function

If the range of addresses that cause a hardware break (including event breaks) is set to the address of the current system stack pointer or to an area that contains the stack pointer, execution will break after each instruction regardless of whether the user program actually contains data access instructions.

To prevent this, do not set (word) access to the area containing the address of the system stack pointer as the target of the hardware break (including an event breaks).

Operand break

It may cause malfunctions if a stack pointer exists in the area which is set as the DSU operand break. Do not set the access to the areas containing the address of system stack pointer as a target of data event break.

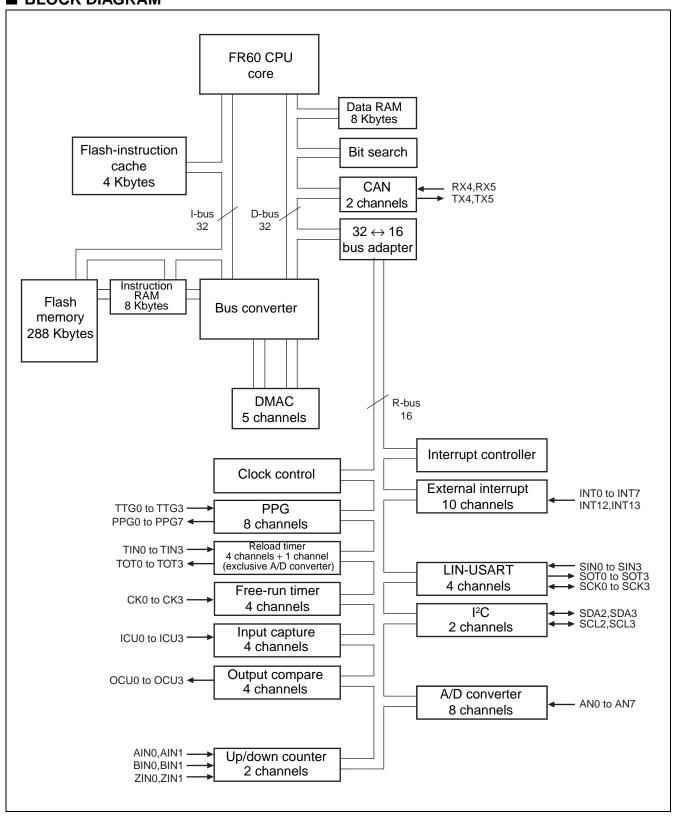
• Notes on PS register

As the PS register is processed in advance by some instructions, when the debugger is being used, the following exception handling may result in execution breaking in an interrupt handling routine or the displayed values of the flags in the PS register being updated.

As the microcontroller is designed to carry out reprocessing correctly upon returning from such an EIT event, the operation before and after the EIT always proceeds according to specification.

- 1) The following behavior may occur if any of the following occurs in the instruction immediately after a DIV0U/DIV0S instruction:
 - (a) a user interrupt or NMI is accepted; (b) single-step execution is performed; or (c) execution breaks due to a data event or from the emulator menu.
 - -D0 and D1 flags are updated in advance.
 - -An EIT handling routine (user interrupt/NMI or emulator) is executed.
 - -Upon returning from the EIT, the DIV0U/DIV0S instruction is executed and the D0 and D1 flags are updated to the same values as those in 1).
- 2) The following behavior occurs when an ORCCR, STILM, MOV Ri or PS instruction is executed to enable a user interrupt or NMI source while that interrupt is in the active state.
 - -The PS register is updated in advance.
 - -An EIT handling routine (user interrupt/NMI or emulator) is executed.
 - -Upon returning from the EIT, the above instructions are executed and the PS register is updated to the same value as in 1).

■ BLOCK DIAGRAM



■ CPU AND CONTROL UNIT

Internal architecture

The FR family CPU is a high performance core that is designed based on the RISC architecture with advanced instructions for embedded applications.

1. Features

- Adoption of RISC architecture
 Basic instruction: 1 instruction per cycle
- General-purpose registers: 32-bit x 16 registers
- 4 Gbytes linear memory space
- Multiplier installed
 - 32-bit × 32-bit multiplication: 5 cycles 16-bit × 16-bit multiplication: 3 cycles
- Enhanced interrupt processing function Quick response speed (6 cycles)
 Multiple-interrupt support Level mask function (16 levels)
- Enhanced instructions for I/O operation Memory-to-memory transfer instruction Bit processing instruction
- Basic instruction word length: 16 bits
- Low-power consumption SLEEP mode/STOP mode

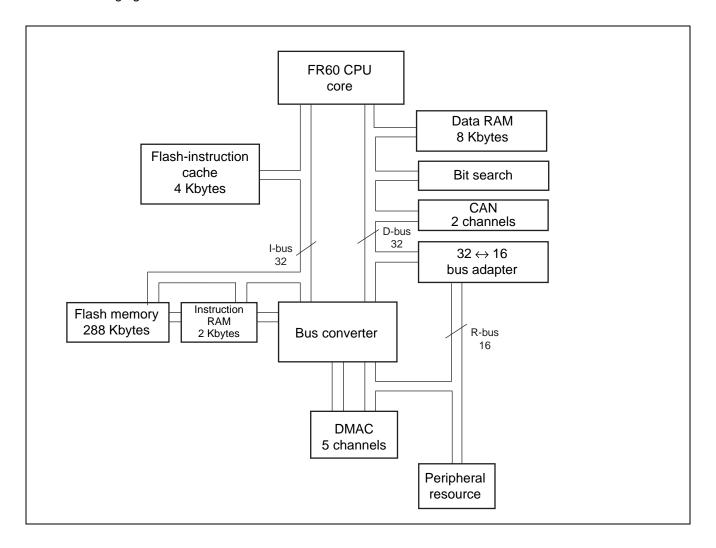
2. Internal architecture

The FR family CPU uses the Harvard architecture in which the instruction bus and data bus are independent of each other.

A 32-bit \leftrightarrow 16-bit bus adapter is connected to the 32-bit bus (D-bus) to provide an interface between the CPU and peripheral resources.

A Harvard \leftrightarrow Princeton bus converter is connected to both the I-bus and D-bus to provide an interface between the CPU and the bus controller.

The following figure shows the internal architecture structure.

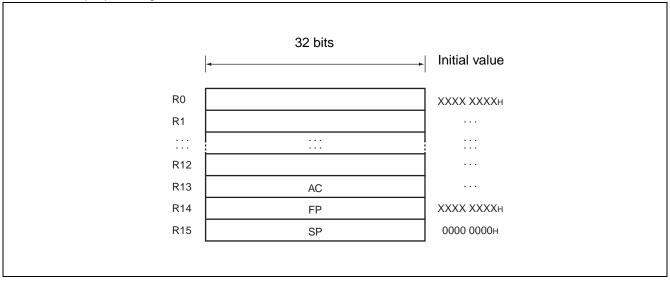


3. Programming model• Basic programming model

		32 bits	
		 →	Initial value
(R0		XXXX XXXXH
	R1		
	:::	:::	:::
General-purpose registers <	R12		
	R13	AC	
	R14	FP	XXXX XXXXH
	R15	SP	0000 0000н
Program status			
Program counter	PC		
	RS	ILM SCR CCR	
Table base register	TBR		
Return pointer	RP		
System stack pointer	SSP		
User stack pointer	USP		
Multiply and divide result	MDH		
registers	MDL		

4. Registers

General-purpose register



Registers R0 to R15 are general-purpose registers. These registers can be used as accumulators for computation operations and as pointers for memory access.

Enhanced commands are provided for some of the 16 registers to enable their use for particular applications.

R13: Virtual accumulator

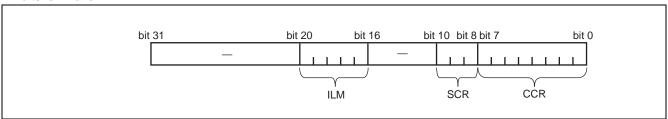
R14 : Frame pointer R15 : Stack pointer

Initial values at reset are undefined for R0 to R14. The value for R15 is 00000000H (SSP value).

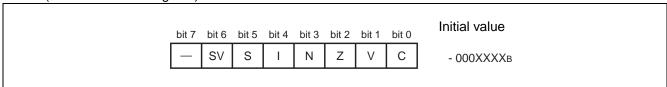
• PS (Program Status)

This register holds the program status, and is divided into three parts, ILM, SCR, and CCR.

All undefined bits (-) in the diagram are reserved bits. The values are always read "0". Write access to these bits is invalid.



• CCR (Condition Code Register)

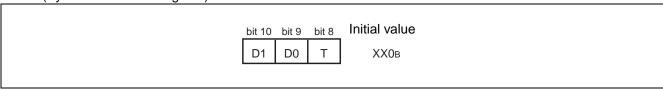


SV : Supervisor S : Stack flag

I : Interrupt enable flagN : Negative enable flag

Z : Zero flagV : Overflow flagC : Carry flag

 SCR (System Condition Registe 	• SCR	(System	Condition	Register
---	-------	---------	-----------	----------



Flag for step multiplication (D1, D0)

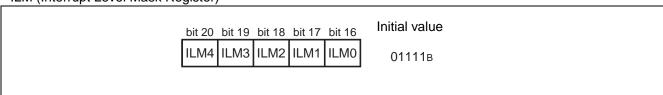
This flag stores interim data during execution of step multiplication.

Step trace trap flag (T)

This flag indicates whether the step trace trap is enabled or disabled.

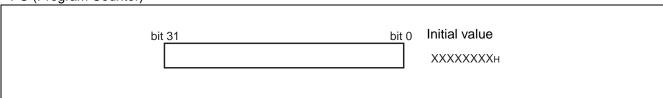
The step trace trap function is used by emulators. When an emulator is in use, it cannot be used in execution of user programs.

• ILM (Interrupt Level Mask Register)



This register stores interrupt level mask values, and the values stored in ILM4 to ILM0 are used for level masking. The register is initialized to value "01111_B" at reset.

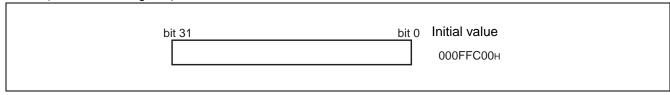
• PC (Program Counter)



The program counter indicates the address of the instruction that is being executed.

The initial value at reset is undefined.

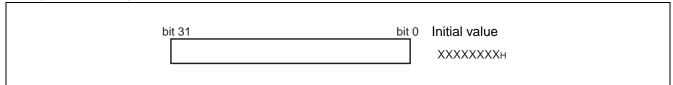
• TBR (Table Base Register)



The table base register stores the starting address of the vector table used in EIT processing.

The initial value at reset is 000FFC00_H.

• RP	(Return	Pointer)
------	---------	----------



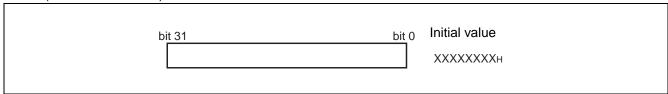
The return pointer stores the address to return from subroutines.

During execution of a CALL instruction, the PC value is transferred to this RP register.

During execution of a RET instruction, the contents of the RP register are transferred to PC.

The initial value at reset is undefined.

• USP (User Stack Pointer)



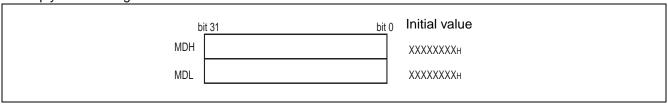
When the S flag is "1", the user stack pointer functions as the R15 register.

• The USP register can also be explicitly specified.

The initial value at reset is undefined.

• This register cannot be used with RETI instructions.

• Multiply & divide registers



These registers are for multiplication and division, and are each 32 bits in length.

The initial value at reset is undefined.

■ MODE SETTING

In the FR family, the mode pins (MD2, MD1, MD0) and the mode register (MODR) are used to set the operating mode.

1. Mode pins

The three pins MD2, MD1, MD0 are used to specify the mode vector fetch.

Settings other than shown in the table are prohibited.

M	Mode pins*		Mode name	Reset vector	Remarks	
MD2	MD1	MD0	Wiode Haine	access area	Remarks	
0	0	0	Internal ROM mode vector	Internal		
0	0	1	External ROM mode vector	External	Not allowed	

^{*:} Always use MD3 with "0".

2. Mode register (MODR)

The data written to the mode register using mode vector fetch is called mode data.

After the mode register (MODR) is set, the device operates according to the operation mode set in this register.

The mode register is set by all reset sources. User programs cannot write data to the mode register.

Rewriting is allowed in the emulator mode. In this case, use an 8-bit length data transfer instruction.

Data cannot be written by the transfer instruction of the 16/32-bit length.

Be sure to set these bits to "00000111_B".

Operation is not guaranteed when any value other than "00000111_B" is set.

Note: The mode data needs to be allocated in 000FFFF8_H as byte data. The mode data (00000111_B) must be allocated in bit 31 to bit 24, as the FR family uses the big endian architecture.

■ RECOMMENDED SETTING

1. Setting of PLL and clock gear

Recommended setting of PLL division and clock gear

Clock input	PLL multiplied setting		Clock gear setting		PLL (vco) output (X)	Base clock
[MHz]	DIVM	DIVN	DIVG	MULG	[MHz]	[MHz]
4	2	20	16	20	160	80
4	2	19	16	20	152	76
4	2	18	16	20	144	72
4	2	17	16	16	136	68
4	2	16	16	16	128	64
4	2	15	16	16	120	60
4	2	14	16	16	112	56
4	2	13	16	12	104	52
4	2	12	16	12	96	48
4	2	11	16	12	88	44
4	4	10	16	24	160	40
4	4	9	16	24	144	36
4	4	8	16	24	128	32
4	4	7	16	24	112	28
4	6	6	16	24	144	24
4	8	5	16	28	160	20
4	10	4	16	32	160	16
4	12	3	16	32	144	12

2. Setting of Flash memory controller

· Setting of flash access timing

For executing programs with a Flash memory, follow the settings below according to the frequency of CPU clock (CLKB). This setting is the most suitable for a high-speed access to the Flash memory.

At Flash memory read operating

CPU clock (CLKB)	ATD	ALEH	EQ	WEXH	WTC
To 24 MHz	0	0	0	0	1
To 48 MHz	0	0	1	0	2
To 80 MHz	1	1	3	0	4

At Flash memory write operating

CPU clock (CLKB)	ATD	ALEH	EQ	WEXH	WTC
To 32 MHz	1	0	1	0	4
To 48 MHz	1	0	3	0	5
To 64 MHz	1	1	3	0	6
To 80 MHz	1	1	3	0	7

3. Setting of clock modulator

The setting values in the table are defined within the rages of base clock frequency; 32 MHz to 80 MHz. The Flash memory access needs to be configured according to the Fmax.

PLL and clock gear need to be configured according to the base clock.

Setting of clock modulator

Modulation (k)	Internal parameter (N)	CMPR [hex]	Base clock [MHz]	Fmin [MHz]	Fmax [MHz]
1	3	026F	80	72.6	89.1
1	3	026F	76	69.1	84.5
1	5	02AE	76	65.3	90.8
2	3	046E	76	65.3	90.8
1	3	026F	72	65.5	79.9
1	5	02AE	72	62	85.8
1	7	02ED	72	58.8	92.7
2	3	046E	72	62	85.8
1	3	026F	68	62	75.3
1	5	02AE	68	58.7	80.9
1	7	02ED	68	55.7	87.3
1	9	032C	68	53	95
2	3	046E	68	58.7	80.9
2	5	04AC	68	53	95
3	3	066D	68	55.7	87.3
4	3	086C	68	53	95
1	3	026F	64	58.5	70.7
1	5	02AE	64	55.3	75.9
1	7	02ED	64	52.5	82
1	9	032C	64	49.9	89.1
2	3	046E	64	55.3	75.9
2	5	04AC	64	49.9	89.1
3	3	066D	64	52.5	82
4	3	086C	64	49.9	89.1
1	3	026F	60	54.9	66.1
1	5	02AE	60	51.9	71
1	7	02ED	60	49.3	76.7
1	9	032C	60	46.9	83.3
2	3	046E	60	51.9	71
2	5	04AC	60	46.9	83.3
3	3	066D	60	49.3	76.7

Modulation (k)	Internal parameter (N)	CMPR [hex]	Base clock [MHz]	Fmin [MHz]	Fmax [MHz]
4	3	086C	60	46.9	83.3
5	3	0A6B	60	44.7	91.3
1	3	026F	56	51.4	61.6
1	5	02AE	56	48.6	66.1
1	7	02ED	56	46.1	71.4
1	9	032C	56	43.8	77.6
1	11	036B	56	41.8	84.9
1	13	03AA	56	39.9	93.8
2	3	046E	56	48.6	66.1
2	5	04AC	56	43.8	77.6
2	7	04EA	56	39.9	93.8
3	3	066D	56	46.1	71.4
4	3	086C	56	43.8	77.6
5	3	0A6B	56	41.8	84.9
1	3	026F	52	47.8	57
1	5	02AE	52	45.2	61.2
1	7	02ED	52	42.9	66.1
1	9	032C	52	40.8	71.8
1	11	036B	52	38.8	78.6
1	13	03AA	52	37.1	86.8
2	3	046E	52	45.2	61.2
2	5	04AC	52	40.8	71.8
2	7	04EA	52	37.1	86.8
3	3	066D	52	42.9	66.1
3	5	06AA	52	37.1	86.8
4	3	086C	52	40.8	71.8
5	3	0A6B	52	38.8	78.6
6	3	0C6A	52	37.1	86.8
1	3	026F	48	44.2	52.5
1	5	02AE	48	41.8	56.4
1	7	02ED	48	39.6	60.9
1	9	032C	48	37.7	66.1
1	11	036B	48	35.9	72.3
1	13	03AA	48	34.3	79.9
1	15	03E9	48	32.8	89.1



Modulation (k)	Internal parameter (N)	CMPR [hex]	Base clock [MHz]	Fmin [MHz]	Fmax [MHz]
2	3	046E	48	41.8	56.4
2	5	04AC	48	37.7	66.1
2	7	04EA	48	34.3	79.9
3	3	066D	48	39.6	60.9
3	5	06AA	48	34.3	79.9
4	3	086C	48	37.7	66.1
5	3	0A6B	48	35.9	72.3
6	3	0C6A	48	34.3	79.9
7	3	0E69	48	32.8	89.1
1	3	026F	44	40.6	48.1
1	5	02AE	44	38.4	51.6
1	7	02ED	44	36.4	55.7
1	9	032C	44	34.6	60.4
1	11	036B	44	33	66.1
1	13	03AA	44	31.5	73
1	15	03E9	44	30.1	81.4
2	3	046E	44	38.4	51.6
2	5	04AC	44	34.6	60.4
2	7	04EA	44	31.5	73
3	3	066D	44	36.4	55.7
3	5	06AA	44	31.5	73
4	3	086C	44	34.6	60.4
4	5	08A8	44	28.9	92.1
5	3	0A6B	44	33	66.1
6	3	0C6A	44	31.5	73
7	3	0E69	44	30.1	81.4
1	3	026F	40	37	43.6
1	5	02AE	40	34.9	46.8
1	7	02ED	40	33.1	50.5
1	9	032C	40	31.5	54.8
1	11	036B	40	30	59.9
1	13	03AA	40	28.7	66.1
1	15	03E9	40	27.4	73.7
2	3	046E	40	34.9	46.8
2	5	04AC	40	31.5	54.8

(Continued)

DS07-16607-4E



Modulation (k)	Internal parameter (N)	CMPR [hex]	Base clock [MHz]	Fmin [MHz]	Fmax [MHz]
2	7	04EA	40	28.7	66.1
2	9	0528	40	26.3	83.3
3	3	066D	40	33.1	50.5
3	5	06AA	40	28.7	66.1
3	7	06E7	40	25.3	95.8
4	3	086C	40	31.5	54.8
4	5	08A8	40	26.3	83.3
5	3	0A6B	40	30	59.9
6	3	0C6A	40	28.7	66.1
7	3	0E69	40	27.4	73.7
8	3	1068	40	26.3	83.3
1	3	026F	36	33.3	39.2
1	5	02AE	36	31.5	42
1	7	02ED	36	29.9	45.3
1	9	032C	36	28.4	49.2
1	11	036B	36	27.1	53.8
1	13	03AA	36	25.8	59.3
1	15	03E9	36	24.7	66.1
2	3	046E	36	31.5	42
2	5	04AC	36	28.4	49.2
2	7	04EA	36	25.8	59.3
2	9	0528	36	23.7	74.7
3	3	066D	36	29.9	45.3
3	5	06AA	36	25.8	59.3
3	7	06E7	36	22.8	85.8
4	3	086C	36	28.4	49.2
4	5	08A8	36	23.7	74.7
5	3	0A6B	36	27.1	53.8
6	3	0C6A	36	25.8	59.3
7	3	0E69	36	24.7	66.1
8	3	1068	36	23.7	74.7
9	3	1267	36	22.8	85.8
1	3	026F	32	29.7	34.7
1	5	02AE	32	28	37.3
1	7	02ED	32	26.6	40.2



Modulation (k)	Internal parameter (N)	CMPR [hex]	Base clock [MHz]	Fmin [MHz]	Fmax [MHz]
1	9	032C	32	25.3	43.6
1	11	036B	32	24.1	47.7
1	13	03AA	32	23	52.5
1	15	03E9	32	22	58.6
2	3	046E	32	28	37.3
2	5	04AC	32	25.3	43.6
2	7	04EA	32	23	52.5
2	9	0528	32	21.1	66.1
2	11	0566	32	19.5	89.1
3	3	066D	32	26.6	40.2
3	5	06AA	32	23	52.5
3	7	06E7	32	20.3	75.9
4	3	086C	32	25.3	43.6
4	5	08A8	32	21.1	66.1
5	3	0A6B	32	24.1	47.7
5	5	0AA6	32	19.5	89.1
6	3	0C6A	32	23	52.5
7	3	0E69	32	22	58.6
8	3	1068	32	21.1	66.1
9	3	1267	32	20.3	75.9
10	3	1466	32	19.5	89.1

■ MEMORY SPACE

1. Memory space

The FR family has 4 Gbytes of logical address space (2³² addresses) available to the CPU by linear access.

• Direct addressing area

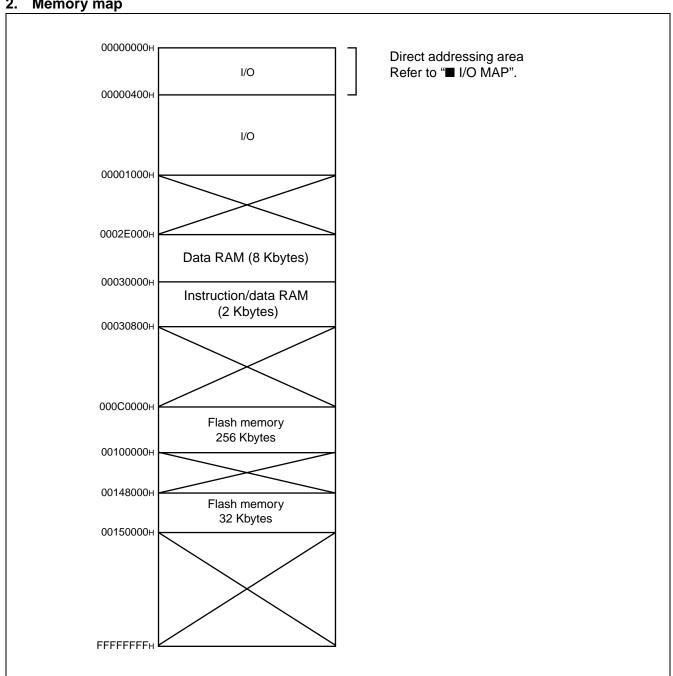
The following address space area is used for I/O.

This area is called direct addressing area, and the address of an operand can be specified directly in an instruction.

The size of directly addressable area depends on the length of the data to be accessed as shown below.

Byte data access : 000H to 0FFH Half word access : 000H to 1FFH Word data access : 000H to 3FFH

Memory map



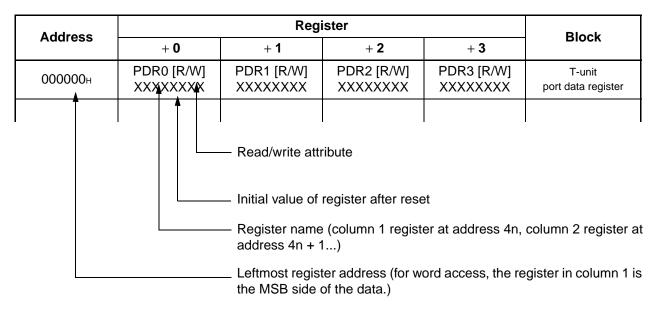
3. Flash memory sector configuration

	MDOAFACONO
addr	MB91F463NC
оот 0014:FFFFн	
0014:Е000н	SA7(8 Kbytes)
0014:DFFFн	0.4.0(0.1(h.:.t)
0014:С000н	SA6(8 Kbytes)
0014:BFFFн	CAE(9 Khytoo)
0014:А000н	SA5(8 Kbytes)
0014:9FFFн	SA4(8 Kbytes)
0014:8000н	e/(T(GT(B)(GG)
0014:7FFFн	SA3(8 Kbytes)
0014:6000н 0014:5FFFн	` , ,
0014:35556	SA2(8 Kbytes)
0014:3FFFн	
0014:2000н	SA1(8 Kbytes)
0014:1FFFн	0.10(0.14)
0014:0000н	SA0(8 Kbytes)
0013:FFFFн	CA22(64 Khytaa)
0013:0000н	SA23(64 Kbytes)
0012:FFFFн	SA22(64 Kbytes)
0012:0000н	6/122(04 Noytes)
0011:FFFFн	SA21(64 Kbytes)
0011:0000н 0010:FFFFн	
0010:РЕРЕН	SA20(64 Kbytes)
0010.0000н 000F:FFFFн	
000F:0000н	SA19(64 Kbytes)
000E:FFFFн	0.4.0/0.4.1/1 /)
000Е:0000н	SA18(64 Kbytes)
000D:FFFFн	SA17(64 Kbytes)
000D:0000н	OATT (04 Rbytes)
000С:FFFFн	SA16(64 Kbytes)
000С:0000н	(0.11.0)100)
000B:FFFFн 000B:0000н	SA15(64 Kbytes)
000Б.0000H 000А:FFFFн	, , ,
000А:1111н	SA14(64 Kbytes)
0009:FFFFн	0.1.0(0.1.1(1)
0009:0000н	SA13(64 Kbytes)
0008:FFFFн	SA12(64 Kbytes)
0008:0000н	SA12(64 Rbyles)
0007:FFFFн	SA11(64 Kbytes)
0007:0000н	Critical Region)
0006:FFFFн	SA10(64 Kbytes)
0006:0000н 0005:FFFFн	
0005:ГЕГЕН	SA9(64 Kbytes)
0003.0000н 0004:FFFFн	
0004:11111н	SA8(64 Kbytes)
223000	addr+0 addr+1 addr+2 addr+3
16-bit write mode	dat[31:16] dat[15:0]
32-bit read mode	dat[31:0]
	· · ·

The shaded area is unusable.

Note: MB91F463NC has a different sector map for the flash memory to that of MB91F463NA. The sector map showed above is suited for MB91F463NC, not for MB91F463NA.

■ I/O MAP



Note: Initial values of register bits are represented as follows:

- " 1 " : Initial value " 1 "
- " 0 " : Initial value " 0 "
- " X ": Initial value " undefined "
- " " : No physical register at this location

Access is prohibited to areas where the data access attributes are undefined.

Address		Reg	ister		Block		
Address	+0	+1	+2	+2 +3			
000000н to 000008н		Reserved					
00000Сн	Rese	erved	PDR14 [R/W] XXXX	PDR15 [R/W] XXXX			
000010н	Reserved	PDR17 [R/W] XXXXXXXX	Rese	erved	R-bus		
000014н	PDR20 [R/W] -XXX-XXX	PDR21 [R/W] -XXX-XXX	PDR22 [R/W] XXXX	Reserved	Port Data Register		
000018н	PDR24 [R/W] XXXXXXXX		Reserved				
00001Сн	Reserved	PDR29 [R/W] XXXXXXXX	Rese	erved			
000020н		Rese	erved]		
000024н to 00002Сн		Rese	erved		Reserved		
00002Сн	EIRR0 [R/W] 00000000	ENIR0 [R/W] 00000000		ELVR0 [R/W] 00000000 00000000			
000034н	EIRR1 [R/W] 00000000	ENIR1 [R/W] 00000000	ELVR1 [R/W] 00000000 00000000		External interrupt 12, 13		
000038н	DICR [R/W]	HRCL [R/W] 0 11111	Rese	erved	DLYI/I-unit		
00003Сн		Rese	erved		Reserved		
000040н	SCR00 [R/W, W] 00000000	SMR00 [R/W, W] 00000000	SSR00 [R/W, R] 00001000	RDR00/TDR00 [R/W] 00000000	LINLICADTO		
000044н	ESCR00 [R/W] 00000X00	ECCR00 [R/W, R, W] 000000XX	Rese	erved	- LIN-USART0		
000048н	SCR01 [R/W, W] 00000000	SMR01 [R/W, W] 00000000	SSR01 [R/W, R] 00001000	RDR01/TDR01 [R/W] 00000000	LINLIGARTA		
00004Сн	ESCR01 [R/W] 00000X00	ECCR01 [R/W, R, W] 000000XX	Reserved		- LIN-USART1		
000050н	SCR02 [R/W, W] 00000000	SMR02 [R/W, W] 00000000	SSR02 [R/W, R] 00001000	RDR02/TDR02 [R/W] 00000000	LINLIGADTO		
000054н	ESCR02 [R/W] 00000X00	ECCR02 [R/W, R, W] 000000XX	Rese	erved	- LIN-USART2		

A ddws 5 5		Reg	ister		Black
Address	+0	+1	+2	+3	Block
000058н	SCR03 [R/W, W] 00000000	SMR03 [R/W, W] 00000000	SSR03 [R/W, R] 00001000	RDR03/TDR03 [R/W] 00000000	LIN-USART3
00005Сн	ESCR03 [R/W] 00000X00	ECCR03 [R/W, R, W] 000000XX	Rese	erved	LIN-OSAINTS
000060н to 00007Сн		Rese	erved		Reserved
000080н	BGR100 [R/W] 00000000	BGR000 [R/W] 00000000	BGR101 [R/W] 00000000	BGR001 [R/W] 00000000	
000084н	BGR102 [R/W] 00000000	BGR002 [R/W] 00000000	BGR103 [R/W] 00000000	BGR003 [R/W] 00000000	Baud rate Generator LIN-USART0 to 3
000088н, 00008Сн		Rese	erved		
000090н to 0000FCн		Reserved			
000100н		0 [R/W] 00010000	Reserved	GCN20 [R/W] 0000	PPG Control 0 to 3
000104н		[R/W] 00010000	Reserved	GCN21 [R/W] 0000	PPG Control 4 to 7
000108н		Rese	erved		Reserved
000110н	PTMR 11111111	00 [R] 11111111	PCSR XXXXXXXX	00 [W] XXXXXXX	PPG 0
000114н	PDUT00 [W] XXXXXXXX XXXXXXX		PCNH00 [R/W] 0000000 -	PCNL00 [R/W] 000000 - 0	FFGU
000118н	PTMR01 [R] PCSR01 [W] 11111111 XXXXXXXX XXXXXXXX			DDC 4	
00011Сн	PDUT01 [W] XXXXXXXX XXXXXXX		PCNH01 [R/W] 0000000 -	PCNL01 [R/W] 000000 - 0	PPG 1
000120н	PTMR 11111111	02 [R] 11111111	PCSR XXXXXXXX	02 [W] XXXXXXXX	PPG 2
000124н		02 [W] XXXXXXXX	PCNH02 [R/W] 0000000 -	PCNL02 [R/W] 000000 - 0	FFG 2

Address		Block			
Address	+0	+1	+2 +3		DIOCK
000128н	PTMR 11111111			03 [W] XXXXXXXX	
00012Сн	PDUT(XXXXXXXX	O3 [W] XXXXXXXX	PCNH03 [R/W] 0000000 -	PCNL03 [R/W] 000000 - 0	PPG 3
000130н		04 [R] 11111111		04 [W] XXXXXXXX	PPG 4
000134н	PDUT(XXXXXXXX	04 [W] XXXXXXXX	PCNH04 [R/W] 0000000 -	PCNL04 [R/W] 000000 - 0	PPG 4
000138н	PTMR 11111111	05 [R] 11111111		05 [W] XXXXXXXX	DD0 5
00013Сн	PDUT(XXXXXXXX	05 [W] XXXXXXXX	PCNH05 [R/W] 0000000 -	PCNL05 [R/W] 000000 - 0	PPG 5
000140н		06 [R] 11111111		06 [W] XXXXXXXX	DDC 0
000144н			PCNL06 [R/W] 000000 - 0	PPG 6	
000148н	PTMR 11111111	07 [R] 11111111	PCSR07 [W] XXXXXXXX XXXXXXX		DDC 7
00014Сн		07 [W] XXXXXXXX	PCNH07 [R/W] 0000000 -	PCNL07 [R/W] 000000 - 0	PPG 7
000150н to 00017Сн		Res	erved		Reserved
000180н	Reserved	ICS01 [R/W] 00000000	Reserved	ICS23 [R/W] 00000000	
000184н	IPCP XXXXXXXX	0 [R] XXXXXXXX	IPCP1 [R] XXXXXXXX XXXXXXX		Input Capture 0 to 3
000188н	IPCP XXXXXXXX	2 [R] XXXXXXXX		3 [R] XXXXXXXX	0.10.0
00018Сн	OCS0 ²	[R/W] 0000 00	OCS23 [R/W]		
000190н	OCCP0 [R/W] XXXXXXXX XXXXXXX			1 [R/W] XXXXXXXX	Output Compare 0 to 3
000194н		2 [R/W] XXXXXXXX		3 [R/W] XXXXXXXX	0 10 0
000198н, 00019Сн		Res	erved		Reserved

A ddroop		Reg	ister		Disak	
Address -	+0	+1	+2	+3	- Block	
0001А0н		Reserved		ADERL [R/W] 00000000		
0001А4н	ADCS1 [R/W] 00000000	ADCS0 [R/W] 00000000	ADCR1 [R] 000000XX	ADCR0 [R] XXXXXXXX	A/D Converter	
0001А8н	ADCT1 [R/W] 00010000	ADCT0 [R/W] 00101100	ADSCH [R/W] 00000	ADECH [R/W] 00000	-	
0001АСн		Rese	erved		Reserved	
0001В0н		RO [W] XXXXXXXX		0 [R] XXXXXXXX	Reload Timer 0	
0001В4н	Rese	erved	TMCSRH0 [R/W] 00000	TMCSRL0 [R/W] 0 - 000000	(PPG0, PPG1)	
0001В8н		R1 [W] XXXXXXXX		1 [R] XXXXXXXX	Reload Timer 1	
0001ВСн	Reserved		TMCSRH1 [R/W] 00000	TMCSRL1 [R/W] 0 - 000000	(PPG2, PPG3)	
0001С0н		R2 [W] XXXXXXXX		2 [R] XXXXXXXX	Reload Timer 2	
0001С4н	Rese	erved	TMCSRH2 [R/W] 00000	TMCSRL2 [R/W] 0 - 000000	(PPG4, PPG5)	
0001С8н		R3 [W] XXXXXXXX		3 [R] XXXXXXXX	Reload Timer 3	
0001ССн	Rese	erved	TMCSRH3 [R/W] 00000	TMCSRL3 [R/W] 0 - 000000	(PPG6, PPG7)	
0001D0н to 0001E7н	Reserved				Reserved	
0001Е8н	TMRLR7 [W] TMR7 [R] XXXXXXXXX XXXXXXXXX		Poload Timor 7			
0001ЕСн	Rese	erved	TMCSRH7 [R/W] 00000	TMCSRL7 [R/W] 0 - 000000	Reload Timer 7 (A/D converter)	
0001F0н	TCDT0 XXXXXXXX	[R/W] XXXXXXXX	Reserved	TCCS0 [R/W] 00000000	Free-run Timer 0 (ICU0, ICU1)	

A -1 -1		Disale			
Address	+0	+1	+2	+3	Block
0001F4н	TCDT1 XXXXXXXX		Reserved	TCCS1 [R/W] 00000000	Free-run Timer 1 (ICU2, ICU3)
0001F8н	TCDT2 XXXXXXXX		Reserved	TCCS2 [R/W] 00000000	Free-run Timer 2 (OCU0, OCU1)
0001FСн	TCDT3 XXXXXXXX		Reserved	TCCS3 [R/W] 00000000	Free-run Timer 3 (OCU2, OCU3)
000200н	000	DMACA0 00000 0000XXXX X	XXXXXXX XXXXX	ΚΧΧ	
000204н	000	DMACB0 000000 00000000 X		XXX	
000208н	000	DMACA1 00000 0000XXXX X		ΚΧΧ	
00020Сн	000	DMACB1		XXX	
000210н	000	DMACA2 00000 0000XXXX X		ΚΧΧ	
000214н	000	DMACB2 000000 00000000 X		XX	
000218н	000	DMACA3 00000 0000XXXX X		ΚΧΧ	DMAC
00021Сн	000				
000220н	000	DMACA4 00000 0000XXXX X		ΚΧΧ	
000224н	000	DMACB4 000000 00000000 X		XXX	
000228н to 00023Сн		Rese	erved		
000240н	DMACR [R/W] 0 0000		Reserved		
000244н to 0002FCн		Reserved			
000300н	UDRC1 [W] 00000000	UDRC0 [W] 00000000	UDCR1 [R] 00000000	UDCR0 [R] 00000000	/5
000304н	UDCCH0 [R/W] 00000000	UDCCL0 [R/W] 00001000	Reserved	UDCS0 [R/W] 00000000	Up/Down Counter 0, 1
000308н	UDCCH1 [R/W] 00000000	UDCCL1 [R/W] 00001000	Reserved	UDCS1 [R/W] 00000000	
00030Сн to	Reserved				Reserved
000364н					(Continued

Address		Block			
Address	+0	+1	+2	+3	BIOCK
000368н	IBCR2 [R/W] 00000000	IBSR2 [R] 00000000	ITBAH2 [R/W] 00	ITBAL2 [R/W] 00000000	
00036Сн	ITMKH2 [R/W] 00 11	ITMKL2 [R/W] 11111111	ISMK2 [R/W] 01111111	ISBA2 [R/W] - 0000000	I ² C 2
000370н	Reserved	IDAR2 [R/W] 00000000	ICCR2 [R/W] - 0011111	Reserved	
000374н	IBCR3 [R/W] 00000000	IBSR3 [R] 00000000	ITBAH3 [R/W] 00	ITBAL3 [R/W] 00000000	
000378н	ITMKH3 [R/W] 00 11	ITMKL3 [R/W] 11111111	ISMK3 [R/W] 01111111	ISBA3 [R/W] - 0000000	I ² C 3
00037Сн	Reserved	IDAR3 [R/W] 00000000	ICCR3 [R/W] - 0011111	Reserved	
000380н to 00038Сн		Rese	erved		Reserved
000390н	ROM: 11111111		Rese	erved	ROM Select Register
000394н to 0003ECн			Reserved		
0003F0н	XXXX	BSD0 XXXXX XXXXXXXX	[W] XXXXXXXX XXXX	(XXX	
0003F4н	XXXX	BSD1 XXXXX XXXXXXX	[R/W] XXXXXXXX XXXX	(XXX	Bit Search
0003F8н	XXXX	BSDC XXXXX XXXXXXXX	[W] XXXXXXXX XXXX	(XXX	Module
0003FСн	XXXX	BSRF (XXXX XXXXXXX	R [R] XXXXXXXX XXXX	(XXX	
000400н to 00043Сн		Rese	erved		Reserved
000440н	ICR00 [R/W] 11111	ICR01 [R/W] 11111	ICR02 [R/W] 11111	ICR03 [R/W] 11111	
000444н	ICR04[R/W] 11111	ICR05 [R/W] 11111	ICR06 [R/W] 11111	ICR07 [R/W] 11111	
000448н	ICR08 [R/W] 11111	ICR09 [R/W] 11111	ICR10[R/W] 11111	ICR11 [R/W] 11111	Interrupt Control Unit
00044Сн	ICR12 [R/W] 11111	ICR13[R/W] 11111	ICR14[R/W] 11111	ICR15[R/W] 11111	Offic
000450н	ICR16[R/W] 11111	ICR17[R/W] 11111	ICR18 [R/W] 11111	ICR19 [R/W] 11111	

A -l -l		Reg	ister		Disal
Address	+0	+1	+2	+3	Block
000454н	ICR20 [R/W] 11111	ICR21 [R/W] 11111	ICR22 [R/W] 11111	ICR23 [R/W] 11111	
000458н	ICR24[R/W] 11111	ICR25[R/W] 11111	ICR26[R/W] 11111	ICR27[R/W] 11111	
00045Сн	ICR28[R/W] 11111	ICR29 [R/W] 11111	ICR30[R/W] 11111	ICR31[R/W] 11111	
000460н	ICR32[R/W] 11111	ICR33[R/W] 11111	ICR34[R/W] 11111	ICR35[R/W] 11111	
000464н	ICR36[R/W] 11111	ICR37[R/W] 11111	ICR38 [R/W] 11111	ICR39 [R/W] 11111	
000468н	ICR40[R/W] 11111	ICR41[R/W] 11111	ICR42 [R/W] 11111	ICR43 [R/W] 11111	Interrupt Control Unit
00046Сн	ICR44[R/W] 11111	ICR45[R/W] 11111	ICR46[R/W] 11111	ICR47[R/W] 11111	O m
000470н	ICR48 [R/W] 11111	ICR49 [R/W] 11111	ICR50 [R/W] 11111	ICR51 [R/W] 11111	
000474н	ICR52[R/W] 11111	ICR53[R/W] 11111	ICR54[R/W] 11111	ICR55[R/W] 11111	
000478н	ICR56 [R/W] 11111	ICR57[R/W] 11111	ICR58 [R/W] 11111	ICR59 [R/W] 11111	
00047Сн	ICR60[R/W] 11111	ICR61 [R/W] 11111	ICR62 [R/W] 11111	ICR63 [R/W] 11111	
000480н	RSRR [R/W] 10000000	STCR [R/W] 001100-1	TBCR [R/W] 00XXXX00	CTBR [W] XXXXXXXX	Clock Control
000484н	CLKR [R/W] 000	WPR [W] XXXXXXXX	DIVR0 [R/W] 00000011	DIVR1 [R/W] 00000000	Unit
000488н		Rese	erved		Reserved
00048Сн	PLLDIVM [R/W] 0000	PLLDIVN [R/W] 000000	PLLDIVG [R/W] 0000	PLLMULG [R/W] 00000000	PLL Clock
000490н	PLLCTRL [R/W] 0000	Reserved			Gear Unit
000494н		Rese	Reserved		
000498н	PORTEN [R/W] 00		Reserved		Port Input Enable Control
00049Сн		Rese	erved		Reserved

A .l. l		Reg	ister		Disal	
Address	+0	+1	+2	+3	Block	
0004А0н	Reserved	WTCER [R/W] 00		WTCR [R/W] 00000000 000 - 00 - 0		
0004А4н	Reserved	XXX	WTBR [R/W] XX XXXXXXXX X	XXXXXX	Real Time Clock (Watch Timer)	
0004А8н	WTHR [R/W] 00000	WTMR [R/W] 000000	WTSR [R/W] 000000	Reserved		
0004АСн	Rese	erved	CSCFG [R/W] 0X000000	CMCFG [R/W] 00000000	Clock Monitor	
0004В0н, 0004В4н		Rese	erved		Reserved	
0004В8н	CMPR 000010	[R/W] 11111101	Reserved	CMCR [R/W] - 001 00	Clock	
0004ВСн	CMT1 00000000	[R/W] 1 0000		[R/W] 000000	Modulator	
0004С0н	CANPRE [R/W] 00000000	CANCKD [R/W] 00	Rese	erved	CAN Clock Control	
0004С4н	Reserved	LVDET [R/W] 00000 - 00	HWWDE [R/W] 00	HWWD [R/W, W] 00011000	Low-voltage Detection	
0004С8н	OSCRH [R/W] 000 001	OSCRL [R/W] 000	Rese	erved	Main- Oscillation Stabilization	
0004ССн		Reserved				
0004D0н to 0007F8н		Rese	erved		Reserved	
0007FСн	Reserved	MODR [W] XXXXXXXX	Rese	erved	Mode Register	
000800н to 000СFСн		Rese	erved		Reserved	
000D00н to 000D08н		Rese	erved			
000D0Сн	Rese	erved	PDRD14 [R] XXXX	PDRD15 [R] XXXX		
000D10н	Reserved	PDRD17 [R] XXXXXXXX			R-bus Port Data	
000D14н	PDRD20 [R] - XXX- XXX	PDRD21 [R] - XXX- XXX	PDRD22 [R] XXXX	Reserved	Direct Read Register	
000D18н	PDRD24 [R] XXXXXXXX	Reserved				
000D1Cн	Reserved	PDRD29 [R] XXXXXXXX	Rese	erved		
000D20н		Rese	erved		(Continued	

Address		Reg	ister		Block	
Address	+0	+1	BIOCK			
000D24н to 000D3Cн		Rese	erved		Reserved	
000D40н to 000D48н		Rese	erved			
000D4Сн	Rese	erved	DDR14 [R/W] 0000	DDR15 [R/W] 0000		
000D50н	Reserved	DDR17 [R/W] 00000000	Rese	erved	R-bus	
000D54н	DDR20 [R/W] -000- 000	DDR21 [R/W] -000- 000	DDR22 [R/W] 0000	Reserved	Port Direction Register	
000D58н	DDR24 [R/W] 00000000		Reserved	1		
000D5Сн	Reserved	DDR29 [R/W] 00000000	Rese	erved		
000D60н		Rese	erved			
000D64н						
to 000D7Сн		Reserved				
000D80н to 000D88н		Reserved				
000D8Сн	Rese	erved	PFR14 [R/W] 0000	PFR15 [R/W] 0000		
000D90н	Reserved	PFR17 [R/W] 00000000	Rese	erved	R-bus	
000D94н	PFR20 [R/W] -000- 000	PFR21 [R/W] -000- 000	PFR22 [R/W] 0000	Reserved	Port Function Register	
000D98н	PFR24 [R/W] 00000000		Reserved			
000D9Сн	Reserved	PFR29 [R/W] 00000000	Rese	erved		
000DA0н		Rese	erved]	
000DA4н to 000DBCн		Reserved				
000DC0н to 000DC8н		Reserved				
000ДССн	Rese	erved	EPFR14 [R/W] 0000	EPFR15 [R/W] 0000	- Function Register	

A ddrago		Reg	ister		Pleak	
Address	+0	+1	+2	+3	Block	
000DD0н	D0 _H Reserved					
000DD4н	EPFR20 [R/W] - 000- 000					
000DD8н		Rese	erved		Function	
000DDCн		Rese	erved		Register	
000DE0н		Rese	erved			
000DE4н		_			_	
to 000DFC _H		Rese	erved		Reserved	
000E00н to 000E08н		Rese	erved			
000Е0Сн	Rese	erved	PODR14 [R/W] 0000	PODR15 [R/W] 0000		
000Е10н	Reserved	PODR17 [R/W] 00000000	Rese	erved	R-bus Port Output Drive Select Register	
000Е14н	PODR20 [R/W] - 000- 000	PODR21 [R/W] - 000- 000	PODR22 [R/W] 0000	Reserved		
000Е18н	PODR24 [R/W] 00000000		Reserved		_	
000Е1Сн	Reserved	PODR29 [R/W] 00000000	Rese	erved		
000Е20н		Rese	erved			
000E24н to 000E3Cн		Rese	erved		Reserved	
000E40н to 000E48н		Rese	erved			
000Е4Сн	Rese	erved	PILR14 [R/W] 0000	PILR15 [R/W] 0000		
000Е50н	Reserved	PILR17 [R/W] 00000000	Rese	erved	R-bus Pin	
000Е54н	PILR20 [R/W] - 000- 000	PILR21 [R/W] -000- 000	PILR22 [R/W] 0000	Reserved	Input Level Select Register	
000Е58н	PILR24 [R/W] 00000000		Reserved			
000Е5Сн	Reserved	PILR29 [R/W] 00000000	Rese	erved		
000Е60н		Rese	erved		(Continue)	

Address		Block			
Address	+0	+1	+2	+3	Бюск
000E64н to 000E7Cн		Rese	erved		Reserved
000E80н to 000E88н		Rese	erved		
000Е8Сн	Rese	erved	EPILR14 [R/W] 0000	EPILR15 [R/W] 0000	
000Е90н	Reserved	EPILR17 [R/W] 00000000	Rese	erved	R-bus Port Extra Input Level Select
000Е94н	EPILR20 [R/W] - 000- 000	EPILR21 [R/W] - 000- 000	EPILR22 [R/W] 0000	Reserved	Register
000Е98н	EPILR24 [R/W] 00000000		Reserved		
000E9Cн, 000EA0н		Rese	erved		
000EA4н to 000EBCн		Reserved			
000EC0н to 000EC8н		Rese	erved		
000ЕССн	Rese	erved	PPER14 [R/W] 0000	PPER15 [R/W] 0000	
000ЕD0н	Reserved	PPER17 [R/W] 00000000	Rese	erved	R-bus Port Pull-up/down
000ЕD4н	PPER20 [R/W] -000- 000	PPER21 [R/W] -000- 000	PPER22 [R/W] 0000	Reserved	Enable Register
000ЕD8н	PPER24 [R/W] 00000000		Reserved		
000EDCн	Reserved	PPER29 [R/W] 00000000	Rese	erved	
000ЕЕ0н					
000EE4н to 000EFCн		Reserved			
000F00н to 000F08н		Rese	erved		R-bus Port Pull-up/down Control Register

Address		Reg	ister		Block				
Address	+0	+1	+2	+3	БЮСК				
000F0Сн	Rese	erved	PPCR14 [R/W] 1111	PPCR15 [R/W] 1111					
000F10н	Reserved	PPCR17 [R/W] 11111111	Rese	erved					
000F14н	PPCR20 [R/W] -111-111	R-bus Port Pull-up/down Control							
000F18н	PPCR24 [R/W] 11111111		Reserved		Register				
000F1Сн	Reserved	Reserved PPCR29 [R/W] Reserved							
000F20н		Rese	erved						
000F24н to 000F3Сн	Reserved								
001000н	XXX	DMASA0 [R/W] XXXXXXXX XXXXXXXX XXXXXXXX							
001004н	XXX		0 [R/W] XXXXXXXX XXXX	(XXX	DMAC				
001008н	XXX		1 [R/W] XXXXXXXX XXXX	ΚΧΧΧ					
00100Сн	XXX		\1 [R/W] XXXXXXXX XXXX	(XXX					
001010н	XXX		2 [R/W] XXXXXXXX XXXX	(XXX					
001014н	XXX		A2 [R/W] XXXXXXXX XXXX	(XXX	DIVIAC				
001018н	XXX		3 [R/W] XXXXXXXX XXXX	(XXX					
00101Сн	XXX		3 [R/W] XXXXXXXX XXXX	(XXX					
001020н	XXX		4 [R/W] XXXXXXXX XXXX	(XXX					
001024н	XXX		4 [R/W] XXXXXXXX XXXX	(XXX					
001028н to 006FFCн		Rese	erved		Reserved				

Address		Reg	ister		Block	
Address	+0	+1	+2	+3	Block	
007000н	FMCS [R/W] 01101000	FMCR [R/W] 0000	FCHCF	R [R/W] 10000011	Flash Memory/	
007004н	FMWT 11111111	[R/W] 01011101	FMWT2 [R/W] - 101	FMPS [R/W] 000	I-Cache Control	
007008н			C [R]	00	Register	
00700Сн			0 [R/W] 0 00000000 000000	00	I-Cache Non-cacheable	
007010н			1 [R/W]) 00000000 000000	00	area setting Register	
007014н		D			Danasa	
to 00AFFC _H		Kes	erved		Reserved	
00В000н to	BI-F	ROM size is 4 Kbyte	s : 00B000н to 00BF	FFн	BI-ROM 4 Kbytes	
00BFFCн					4 Noytes	
00С000н to		Reserved				
00С3FCн		1100	erved		110001100	
00С400н	CTRLR 00000000			4 [R/W] 00000000		
00С404н	ERRC1 00000000	NT4 [R] 00000000	BTR4 00100011	CAN 4 Control Register		
00С408н	INTR 00000000	4 [R] 00000000	TESTR4 [R/W] 00000000 X0000000			
00С40Сн	BRPE4 00000000	I [R/W] 00000000	Rese	erved		
00С410н	IF1CRE0 00000000			K4 [R/W] 00000000		
00С414н	IF1MSK 11111111		IF1MSK 11111111			
00С418н		24 [R/W] 00000000		14 [R/W] 00000000		
00С41Сн	IF1MCTI 00000000	R4 [R/W] 00000000	erved	CAN 4 IF1 Register		
00С420н	IF1DTA 00000000		IF1DTA2 00000000	24 [R/W] 00000000		
00С424н	IF1DTB ⁻ 00000000		IF1DTB2 00000000	24 [R/W] 00000000		
00С428н, 00С42Сн		Res	erved			



Address		Regi	ister		Block
Address	+0	+1	+2	+3	— BIOCK
00С430н	IF1DTA24 00000000 0			14 [R/W] 00000000	
00С434н	IF1DTB24 00000000 0			IF1DTB14 [R/W] 00000000 00000000	
00С438н, 00С43Сн		Rese	erved		
00С440н	IF2CREQ4 00000000 (K4 [R/W] 00000000	
00С444н	IF2MSK24 11111111 1			14 [R/W] 11111111	
00С448н	IF2ARB24 00000000 0			14 [R/W] 00000000	
00С44Сн	IF2MCTR4 00000000 0		Res	erved	
00С450н	IF2DTA14 00000000 0			IF2DTA24 [R/W] 00000000 00000000	
00С454н	IE2DTB14 [R/M]		IF2DTB 00000000	CAN 4 IF2 Register	
00С458н, 00С45Сн		Rese	erved		
00С460н	IF2DTA24 00000000 0		IF2DTA14 [R/W] 00000000 00000000		
00С464н	IF2DTB24 00000000 0		IF2DTB 00000000		
00С468н to 00С47Сн		Rese	erved		
00С480н	TREQR2 00000000 0			R14 [R] 00000000	
00С484н	TREQR4 00000000 (R34 [R] 00000000	1
00С488н	TREQR6			R54 [R] 00000000	CAN 4
00С48Сн	TREOR84 IR1			R74 [R] 00000000	Status Flags
00С490н	NEWDT2 00000000			0T14 [R] 00000000	
00С494н	NEWDT4 00000000 (0T34 [R] 00000000	

Address		Block				
Address	+0	+1	+2	+2 +3		
00С498н	NEWDT 00000000			DT54 [R] 0 00000000		
00С49Сн	NEWDT 00000000			DT74 [R] 0 00000000		
00С4А0н	INTPND 00000000			ND14 [R] 0 00000000		
00С4А4н	INTPND 00000000			ND34 [R] 0 00000000		
00С4А8н	0000000 0000000			ND54 [R] 0 00000000		
00С4АСн	00000000 00000000 MSGVAL24 [R]			ND74 [R] 0 00000000	CAN 4 Status Flags	
00С4В0н	00000000 00000000 MSGVAL24 [R]			/AL14 [R] 0 00000000		
00С4В4н	MSGVAL 00000000			/AL34 [R] 0 00000000		
00С4В8н	MSGVAL 00000000		MSG\ 0000000			
00С4ВСн	MSGVAL 00000000		MSG\ 0000000			
00С4С0н to 00С4FСн		Rese	erved			
00С500н	CTRLR5 00000000			R5 [R/W] 0 00000000		
00С504н	ERRCN 00000000		BTR5 [R/W] 00100011 00000001		CAN 5	
00С508н	INTR5 00000000			R5 [R/W] X0000000	Control Register	
00С50Сн	BRPE5 00000000		Re	served		
00С510н	IF1CREQ 00000000			SK5 [R/W] 0 00000000		
00С514н	IF1MSK2 11111111			K15 [R/W] 1 11111111		
00С518н	IF1ARB29 00000000	• •	-		CAN 5 IF1 Register	
00С51Сн	IF1MCTR 00000000	• •	Re	served		
00С520н	IF1DTA19			A25 [R/W] 0 00000000		

(Continued)

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A alabasas		Registe	r		Disala
Address	+0 +	1	+2	+3	Block
00С524н	IF1DTB15 [R/W] 00000000 00000000	0		325 [R/W] 0 00000000	
00С528н, 00С52Сн		Reserve	d		
00С530н	IF1DTA25 [R/W] 00000000 00000000	0		A15 [R/W] 0 00000000	CAN 5 IF1 Register
00С534н	IF1DTB25 [R/W] 00000000 00000000	0		315 [R/W] 0 00000000	
00С538н, 00С53Сн					
00С540н	IF2CREQ5 [R/W] 00000000 00000000	1		SK5 [R/W] 0 00000000	
00С544н	IF2MSK25 [R/W] 11111111 11111111	1		K15 [R/W] 11111111	
00С548н	IF2ARB25 [R/W] 00000000 00000000	0	IF2ARE 00000000	CAN 5 IF2 Register	
00С54Сн	IF2MCTR5 [R/W] 00000000 00000000	0	Res		
00С550н	IF2DTA15 [R/W] 00000000 00000000	0	IF2DT/ 00000000		
00С554н	IF2DTB15 [R/W] 00000000 00000000	0	IF2DTE 00000000		
00С558н, 00С55Сн		Reserve	d		
00С560н	IF2DTA25 [R/W] 00000000 00000000	0		A15 [R/W] 0 00000000	
00С564н	IF2DTB25 [R/W] 00000000 00000000	0		315 [R/W] 0 00000000	
00С568н to 00С57Сн		Reserve	d		
00С580н	TREQR25 [R] 00000000 00000000	0		QR15 [R] 0 00000000	
00С584н	TREQR45 [R] 00000000 00000000	0		QR35 [R] 0 00000000	CAN 5 Status Flags
00С588н	TREQR65 [R] 00000000 00000000	0		QR55 [R] 0 00000000	

Address		Reg	ister		Block	
Address	+0	+1	+2	+3	- Block	
00С58Сн	TREQR 00000000			R75 [R] 00000000		
00С590н	NEWDT 00000000			NEWDT15 [R] 00000000 00000000		
00С594н	NEWDT 00000000			0T35 [R] 00000000		
00С598н	NEWDT 00000000			0T55 [R] 00000000		
00С59Сн	NEWDT 00000000			0T75 [R] 00000000		
00С5А0н	INTPND 00000000			D15 [R] 00000000		
00С5А4н	INTPND 00000000			D35 [R] 00000000	CAN 5	
00С5А8н	INTPND 00000000		INTPND55 [R] 00000000 00000000		Status Flags	
00С5АСн		INTPND85 [R] 00000000 00000000		INTPND75 [R] 00000000 00000000		
00С5В0н	MSGVA 00000000		MSGV/ 00000000			
00С5В4н	MSGVA 00000000		MSGV/ 00000000			
00С5В8н	MSGVA 00000000		MSGV/ 00000000			
00С5ВСн	MSGVA 00000000			AL75 [R] 00000000		
00С5С0н to 00ЕFFСн		Rese	erved			
00F000н		BCTRL	[R/W] 11111100 00000	000		
00F004н			[R/W] 00000000 10 0	0000		
00F008н	000	BIAC 00000 00000000	[R] 00000000 000000	000	EDSU / MPU	
00F00Сн	000	BOAC 00000 00000000	[R] 00000000 000000	000		
00F010н	000	BIRQ 00000 00000000	[R/W] 00000000 000000	000		

Adduses		Reg	gister		Disale			
Address —	+0	+1	+2	+3	Block			
00F014н to 00F01Сн	,	Res	erved					
00F020н		BCR0	[R/W] 00 00000000 00000	000				
00F024н		BCR1 [R/W] 00000000 00000000 00000000						
00F028н		BCR2	[R/W] 00 00000000 00000	000	— EDSU/MPU			
00F02Сн			[R/W] 00 00000000 00000	000				
00F030н to 00F03Сн		Res	erved					
00F040н to 00F07Сн		Res	erved		Reserved			
00F080н	XXXXX	BAD0 XXX XXXXXXX	[R/W] XXXXXXXX XX	XXXXX				
00F084н	XXXXX	BAD1 XXX XXXXXXX	[R/W] XXXXXXXX XX	XXXXX				
00F088н	XXXXX	BAD2 XXX XXXXXXX	[R/W] XXXXXXXX XX	xxxxx				
00F08Сн	XXXXX	BAD3 XXX XXXXXXX	[R/W] XXXXXXXX XX	xxxxx				
00F090н	XXXXX	BAD4 XXXX XXXXXXX	[R/W] XXXXXXXX XX	xxxxxx	EDSU / MPU			
00F094н	XXXXX	BAD5 XXXX XXXXXXX	[R/W] XXXXXXXX XX	XXXXXX				
00F098н	XXXXX	BAD6 XXXX XXXXXXX	[R/W] XXXXXXXX XX	XXXXXX				
00F09Сн	XXXXX	BAD7 XXXX XXXXXXX	[R/W] XXXXXXXX XX	XXXXXX				
00F0A0н	XXXXX		[R/W] XXXXXXXX XX	xxxxxx				

Address		Reg	ister		Plank		
Address	+0	+1	+2	+3	Block		
00F0A4н	XXXX	BAD9 XXXX XXXXXXX	[R/W] XXXXXXXX XXX	XXXXX			
00F0A8н	XXXXX	BAD10 XXXX XXXXXXX		XXXXX			
00F0АСн	XXXX	BAD11 XXXX XXXXXXX	L 1	XXXXX			
00F0B0н	XXXXX						
00F0В4н	XXXXX	BAD13 XXXX XXXXXXX		XXXXX	EDSU / MPU		
00F0В8н	XXXXX	BAD14 XXXX XXXXXXX		XXXXX			
00F0ВСн	XXXX	BAD15 XXXX XXXXXXX		XXXXX			
00F0C0н to 00F0FCн		Res	erved				
00F100н to 02DFFCн		Reserved					
02E000н to 02FFFСн	MB91F463NA/F	463NC Data RAM s (data access	ize is 8 Kbytes: 02E is 0 wait cycle)	E000н to 02FFFFн	D-RAM 8 Kbytes		
030000н to 0307FCн		NA/F463NC Instruction 030000 to access is 0 wait cy	o 0307FFн	•	I/D-RAM 2 Kbytes		
030800н to 0BFFFCн		Res	erved		Reserved		
0С0000н to 0DFFFCн		ROMS04 are	a (128 Kbytes)		Flash memory 256 Kbytes		
0E0000н to 0FFFF4н		ROMS05 area (128 Kbytes)					
0FFFF8н			V [R] XXXX _H		Reset/Mode		
0FFFFC _н			/ [R] XXXXн		Vector		
100000н to 147FFСн		Res	erved		Reserved		

Address		Register						
Address	+0	+0 +1 +2 +3						
148000н to 14FFFСн		ROMS07 are	a (32 Kbytes)		Flash memory 32 Kbytes			
148000н to 4FFFFСн		Rese	erved		Reserved			

^{*:} The lower 16 bits (DTC15 to DTC0) of DMACA0 to DMACA4 cannot be accessed in bytes.

■ INTERRUPT SOURCE TABLE

Interrupt source	Inter num		Interru	pt level	Interr	upt vector	Resource
interrupt source	Decimal	Hexa- decimal	Setting register	Register address	Offset	Default vector address	number*1
Reset	0	00	_	_	3FСн	000FFFCн	_
Mode vector	1	01	_	_	3F8н	000FFF8н	_
System reserved	2	02	_	_	3F4н	000FFF4н	_
System reserved	3	03	_	_	3F0н	000FFF0н	_
System reserved	4	04	_	_	3ЕСн	000FFFECн	_
CPU supervisor mode (INT #5 instruction) *2	5	05		_	3Е8н	000FFFE8н	_
Memory protection exception *2	6	06	_	_	3Е4н	000FFFE4н	
System reserved	7	07		_	3Е0н	000FFFE0н	_
System reserved	8	08	_	_	3DСн	000FFFDCн	_
System reserved	9	09		_	3D8н	000FFFD8н	
System reserved	10	0A		_	3D4н	000FFFD4н	
System reserved	11	0B	_	_	3D0н	000FFFD0н	_
System reserved	12	0C	_	_	3ССн	000FFFCCн	
System reserved	13	0D	_	_	3С8н	000FFFC8н	
Undefined instruction exception	14	0E	_	_	3С4н	000FFFC4н	_
NMI request	15	0F	F _H f	ixed	3С0н	000FFFC0н	_
External interrupt 0	16	10	ICR00	440н	3ВСн	000FFFBCн	0, 16
External interrupt 1	17	11	ICKUU	440H	3В8н	000FFFB8н	1, 17
External interrupt 2	18	12	ICR01	441н	3В4н	000FFFB4н	2, 18
External interrupt 3	19	13	ICRUI	441H	3В0н	000FFFB0н	3, 19
External interrupt 4	20	14	ICR02	442н	3АСн	000FFFACн	20
External interrupt 5	21	15	ICR02	44ZH	3А8н	000FFFA8н	21
External interrupt 6	22	16	ICBOS	443н	3А4н	000FFFA4н	22
External interrupt 7	23	17	ICR03	443H	3А0н	000FFFA0н	23
System reserved	24	18	ICR04	444 _H	39Сн	000FFF9Сн	_
System reserved	25	19	ICK04	444	398н	000FFF98н	_
System reserved	26	1A	ICDOE	445	394н	000FFF94н	_
System reserved	27	1B	ICR05	445н	390н	000FFF90н	_
External interrupt 12	28	1C	ICDOS	446	38Сн	000FFF8Сн	
External interrupt 13	29	1D	ICR06	446н	388н	000FFF88н	_
System reserved	30	1E	ICD07	447:	384н	000FFF84н	_
System reserved	31	1F	ICR07	447н	380н	000FFF80н	_

Interrupt source		errupt ımber	Interru	pt level	Interr	upt vector	Resource
interrupt source	Decimal	Hexadecimal	Setting register	Register address	Offset	Default vector address	number*1
Reload timer 0	32	20	ICR08	448н	37Сн	000FFF7Сн	4, 32
Reload timer 1	33	21	ICKUO	440H	378н	000FFF78н	5, 33
Reload timer 2	34	22	ICR09	449н	374н	000FFF74н	34
Reload timer 3	35	23	ICR09	449H	370н	000FFF70н	35
System reserved	36	24	ICD40	440	36Сн	000FFF6Сн	36
System reserved	37	25	ICR10	44Ан	368н	000FFF68н	37
System reserved	38	26	IOD44	440	364н	000FFF64н	38
Reload timer 7	39	27	ICR11	44Вн	360н	000FFF60н	39
Free-run timer 0	40	28	10040	440	35Сн	000FFF5Сн	40
Free-run timer 1	41	29	ICR12	44Сн	358н	000FFF58н	41
Free-run timer 2	42	2A	10040	445	354н	000FFF54н	42
Free-run timer 3	43	2B	ICR13	44Dн	350н	000FFF50н	43
System reserved	44	2C	100.44	44Ен	34Сн	000FFF4Сн	44
System reserved	45	2D	ICR14		348н	000FFF48н	45
System reserved	46	2E	10045	4.45	344н	000FFF44н	46
System reserved	47	2F	ICR15	44Гн	340н	000FFF40н	47
System reserved	48	30	10040	450	33Сн	000FFF3Сн	_
System reserved	49	31	ICR16	450н	338н	000FFF38н	_
System reserved	50	32	10047	454	334н	000FFF34н	
System reserved	51	33	ICR17	451н	330н	000FFF30н	
CAN 4	52	34	10040	450	32Сн	000FFF2Сн	_
CAN 5	53	35	ICR18	452н	328н	000FFF28н	
LIN-USART0 RX	54	36	10040	450	324н	000FFF24н	6, 48
LIN-USART0 TX	55	37	ICR19	453н	320н	000FFF20н	7, 49
LIN-USART1 RX	56	38	IODOO	45.4	31Сн	000FFF1Сн	8, 50
LIN-USART1 TX	57	39	ICR20	454н	318н	000FFF18н	9, 51
LIN-USART2 RX	58	3A	10001		314н	000FFF14н	52
LIN-USART2 TX	59	3B	ICR21	455н	310н	000FFF10н	53
LIN-USART3 RX	60	3C	10500	450	30Сн	000FFF0Сн	54
LIN-USART3 TX	61	3D	ICR22	456н	308н	000FFF08н	55
System reserved	62	3E	10000 **	45-	304н	000FFF04н	_
Delayed interrupt	63	3F	ICR23 *3	457н	300н	000FFF00н	_

Interrupt source	Inter num		Interru	pt level	Interr	upt vector	Resource
interrupt Source	Decimal	Hexa- decimal	Setting register	Register address	Offset	Default vector address	number*1
System reserved *4	64	40	(ICR24)	(450)	2FСн	000FFEFCн	_
System reserved *4	65	41	(ICK24)	(458н)	2F8н	000FFEF8н	_
System reserved	66	42	ICR25	459н	2F4н	000FFEF4н	10, 56
System reserved	67	43	ICR25	439H	2F0н	000FFEF0н	11, 57
System reserved	68	44	ICR26	45Ан	2ЕСн	000FFEEСн	12, 58
System reserved	69	45	ICR20	45AH	2Е8н	000FFEE8н	13, 59
System reserved	70	46	ICD27	45D.	2Е4н	000FFEE4н	60
System reserved	71	47	ICR27	45Вн	2Е0н	000FFEE0н	61
System reserved	72	48	ICDOO	450	2DC _H	000FFEDCн	62
System reserved	73	49	ICR28	45Сн	2D8н	000FFED8н	63
I ² C 2	74	4A	IODOO	450	2D4н	000FFED4н	_
I ² C 3	75	4B	ICR29	45Dн	2D0н	000FFED0н	_
System reserved	76	4C	ICR30	45Ен	2ССн	000FFECCн	64
System reserved	77	4D			2С8н	000FFEC8н	65
System reserved	78	4E	IODO4	455	2С4н	000FFEC4н	66
System reserved	79	4F	ICR31	45Fн	2С0н	000FFEC0н	67
System reserved	80	50	IODOO	400	2ВСн	000FFEBCн	68
System reserved	81	51	ICR32	460н	2В8н	000FFEB8н	69
System reserved	82	52	ICDaa	404	2В4н	000FFEB4н	70
System reserved	83	53	ICR33	461н	2В0н	000FFEB0н	71
System reserved	84	54	IOD04	400	2АСн	000FFEACн	72
System reserved	85	55	ICR34	462н	2А8н	000FFEA8н	73
System reserved	86	56	IODOF	400	2А4н	000FFEA4н	74
System reserved	87	57	ICR35	463н	2А0н	000FFEA0н	75
System reserved	88	58	IODOG	404	29Сн	000FFE9Cн	76
System reserved	89	59	ICR36	464н	298н	000FFE98н	77
System reserved	90	5A	10007	405	294н	000FFE94н	78
System reserved	91	5B	ICR37	465н	290н	000FFE90н	79
Input capture 0	92	5C	10500	400	28Сн	000FFE8Сн	80
Input capture 1	93	5D	ICR38	466н	288н	000FFE88н	81
Input capture 2	94	5E	10500	40-	284н	000FFE84н	82
Input capture 3	95	5F	ICR39	467н	280н	000FFE80н	83

Interrupt source	Inter num		Interru	pt level	Interr	upt vector	Resource
interrupt source	Decimal	Hexa- decimal	Setting register	Register address	Offset	Default vector address	number*1
System reserved	96	60	ICR40	468н	27Сн	000FFE7Сн	84
System reserved	97	61	ICR40	400H	278н	000FFE78н	85
System reserved	98	62	ICR41	469н	274н	000FFE74н	86
System reserved	99	63	ICK41	409H	270н	000FFE70н	87
Output compare 0	100	64	ICD 40	46.4	26Сн	000FFE6Сн	88
Output compare 1	101	65	ICR42	46Ан	268н	000FFE68н	89
Output compare 2	102	66	ICD 42	4CD	264н	000FFE64н	90
Output compare 3	103	67	ICR43	46Вн	260н	000FFE60н	91
System reserved	104	68	100.44	400	25Сн	000FFE5Сн	92
System reserved	105	69	ICR44	46Сн	258н	000FFE58н	93
System reserved	106	6A	100.45	4CD	254н	000FFE54н	94
System reserved	107	6B	ICR45	46Dн	250н	000FFE50н	95
System reserved	108	6C	ICR46	405	24Сн	000FFE4Cн	_
Phase Frequency modulator	109	6D		46Ен	248н	000FFE48н	_
System reserved	110	6E	IOD 47 *4	405	244н	000FFE44н	_
System reserved	111	6F	ICR47 *4	46F _H	240н	000FFE40н	_
PPG0	112	70	100.40	470	23Сн	000FFE3Сн	15, 96
PPG1	113	71	ICR48	470н	238н	000FFE38н	97
PPG2	114	72	ICD 40	474	234н	000FFE34н	98
PPG3	115	73	ICR49	471н	230н	000FFE30н	99
PPG4	116	74	IODEO	470	22Сн	000FFE2Cн	100
PPG5	117	75	ICR50	472н	228н	000FFE28н	101
PPG6	118	76	ICD54	470	224н	000FFE24н	102
PPG7	119	77	ICR51	473н	220н	000FFE20н	103
System reserved	120	78	IODEO	474	21Сн	000FFE1Сн	104
System reserved	121	79	ICR52	474н	218н	000FFE18н	105
System reserved	122	7A	10050	475	214н	000FFE14н	106
System reserved	123	7B	ICR53	475н	210н	000FFE10н	107
System reserved	124	7C	10054	470	20Сн	000FFE0Сн	108
System reserved	125	7D	ICR54	476н	208н	000FFE08н	109
System reserved	126	7E	10055	477	204н	000FFE04н	110
System reserved	127	7F	ICR55	477н	200н	000FFE00н	111

Interrupt source	Inter num	•	Interru	pt level	Interru	upt vector	Resource
interrupt source	Decimal	Hexa- decimal	Setting register	Register address	Offset	Default vector address	number*1
Up/down counter 0	128	80	ICR56	478н	1FCн	000FFDFCн	
Up/down counter 1	129	81	ICKSO	47 OH	1F8 _H	000FFDF8н	_
System reserved	130	82	ICR57	479н	1F4 _H	000FFDF4н	_
System reserved	131	83	ICR5/	479H	1F0н	000FFDF0н	
Real time clock	132	84	ICR58	47Ан	1ЕСн	000FFDECн	
Calibration unit	133	85	ICKS6	4/AH	1Е8н	000FFDE8н	
A/D converter 0	134	86	ICR59	47Вн	1Е4н	000FFDE4н	14, 112
System reserved	135	87	ICKS9	47 DH	1Е0н	000FFDE0н	
System reserved	136	88	ICR60	47Сн	1DC _H	000FFDDCн	
System reserved	137	89	ICROU	47CH	1D8н	000FFDD8н	
Low voltage detection	138	8A	ICR61	47Dн	1D4н	000FFDD4н	_
System reserved	139	8B	ICROI	47 DH	1D0н	000FFDD0н	
Time-base overflow	140	8C	ICR62	47Ен	1ССн	000FFDCCн	
PLL clock gear	141	8D	ICR02	47 EH	1С8н	000FFDC8н	_
DMA controller	142	8E	ICR63	47F _H	1С4н	000FFDC4н	
Main OSC stability wait	143	8F	ICR63	4/FH	1С0н	000FFDC0н	
System reserved	144	90	_	_	1ВСн	000FFDBCн	
Used by the INT instruction	145 to 255	91 to FF	_	_	1В8н to 000н	000FFDB8н to 000FFC00н	_

^{*1:} The peripheral resources to which RN (Resource Number) is assigned are capable of being DMA transfer activation sources. In addition, RN respectively corresponds to an IS (Input Source) of the DMAC channel control register A(DMACA0 to DMACA4), and the IS (Input Source) can be obtained by representing RN in a binary number and adding "1" to the head of it.

^{*2:} Memory Protection Unit (MPU) support

^{*3:} ICR23 can be switched to ICR47 by setting REALOS compatibility bit (address 0C03H ISO[0]).

^{*4:} Used by REALOS

■ ELECTRICAL CHARACTERISTICS

1. Absolute maximum rating

Parameter	Symbol	Rat	ting	Unit	Remarks
Parameter	Symbol	Min	Max	Unit	Remarks
Power supply voltage*1	Vcc	Vss - 0.5	Vss + 6.0	V	
Analog power supply voltage*1	AVcc	Vss - 0.5	Vss + 6.0	V	*2
Analog power supply voltage*1	AVRH	Vss - 0.5	Vss + 6.0	V	*2
Input voltage*1	Vı	Vss - 0.3	Vcc + 0.3	V	*3
Analog pin input voltage*1	VIA	Vss - 0.3	AVcc + 0.3	V	
Output voltage*1	Vo	Vss - 0.3	Vcc + 0.3	V	*3
Maximum clamp current	CLAMP	- 2.0	+2.0	mA	*4
Total maximum clamp current	$\Sigma I_{CLAMP} $	_	20	mA	*4
"L" level maximum output current	lol	_	10	mA	*5
"L" level average output current	lolav	_	4	mA	*6
"L" level total maximum output current	Σ loL	_	100	mA	
"L" level total average output current	Σ lolav	_	50	mA	*7
"H" level maximum output current	Іон	_	- 10	mA	*5
"H" level average output current	loнаv	_	- 4	mA	*6
"H" level total maximum output current	ΣІон	_	- 100	mA	
"H" level total average output current	Σ lohav	_	- 20	mA	*7
Power consumption	Po	_	700	mW	
Operation temperature	т.	-40	+105	°C	When using Vcc = 3.3 V
Operation temperature	Та	-40	+85	°C	When using Vcc = 5.0 V
Storage temperature	Tstg	- 55	+ 125	°C	

^{*1 :} The parameter is based on $V_{SS} = AV_{SS} = 0.0 \text{ V}.$

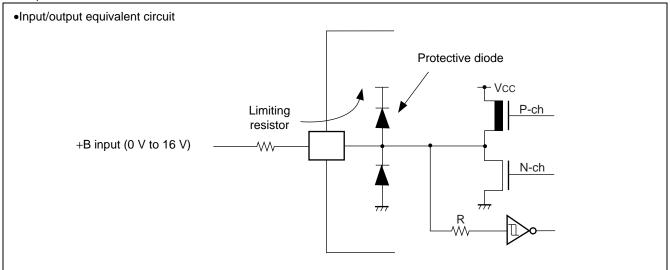
^{*2 :} AVcc and AVRH must not exceed Vcc + 0.3 V, for example, at power on. AVcc must not exceed Vcc.

^{*3 :} V_1 and V_0 must not exceed $V_{CC} + 0.3V$. However, when the maximum value of the current to the input or the current from the input is limited by using outside parts, I_{CLAMP} ratings are applied in place of V_1 ratings.

(Continued)

- *4: Corresponding pins: Pin name P29_0 to P29_7, P24_0 to P24_7, P22_0 to P22_3, P20_0 to P20_2, P20_4 to P20_6, P15_0 to P15_3, P17_0 to P17_7, P21_0 to P21_2, P21_4 to P21_6, P14_0 to P14_3
 - Use within recommended operating conditions.
 - Use at DC voltage (current).
 - The + B signal is an input signal exceeding Vcc voltage. The + B signal should always be applied by connecting a limiting resistor between the + B signal and the microcontroller.
 - The value of the limiting resistor should be set so that the current input to the microcontroller pin does not exceed rated values at any time regardless of instantaneously or constantly when the + B signal is input.
 - Note that when the microcontroller drive current is low, such as in the low power consumption modes, the
 + B input potential can increase the potential at the VCC pin via a protective diode, possibly affecting other
 devices.
 - Note that if the + B signal is input when the microcontroller is off (not fixed at 0 V), since the power is supplied through the pin, the microcontroller may operate incompletely.
 - Note that if the + B signal is input at power-on, since the power is supplied through the pin, the power supply voltage may become the voltage at which a power-on reset does not work.
 - Do not leave + B input pins open.
 - Note that analog input/output pins can input the + B signal only at using as a port.
- *5: Maximum output current is defined as the value of the peak current flowing through any one of the corresponding pins.
- *6 : Average output current is defined as the value of the average current flowing through any one of the corresponding pins for a 100 ms period.
- *7: Total average output current is defined as the value of the average current flowing through all of the corresponding pins for a 100 ms period.

•Sample recommended circuit :



WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

2. Recommended operating conditions

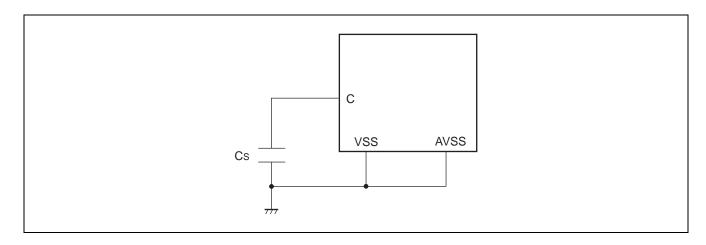
(Vss = AVss = 0.0 V)

Parameter	Symbol	Va	lue	Unit	Remarks	
Faranteter	Зуппоп	Min	Max	Onne	Kemarks	
	Vcc	3.0	3.6	V	When using Vcc = 3.3 V	
Power supply voltage	VCC	4.5	5.5	V	When using Vcc = 5.0 V	
	AVcc	3.0	3.6	V	When using Vcc = 3.3 V	
		4.5	5.5	V	When using Vcc = 5.0 V	
Smoothing capacitor	Cs		.7 vithin ± 50%)	μF	Use a ceramic capacitor or a capacitor that has the similar frequency characteristics. Use a capacitor with a capacitance greater than Cs as the smoothing capacitor on the VCC pin.	
	т	-40	+105	°C	When using Vcc = 3.3 V	
Operating temperature	TA	-40 +85		°C	When using Vcc = 5.0 V	

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

> Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their representatives beforehand.



3. DC characteristics

 $(Vcc = 3.0 \text{ V to } 3.6 \text{ V/ } 4.5 \text{ V to } 5.5 \text{ V}, \text{ Vss} = \text{AVss} = 0 \text{ V}, \text{ T}_{A} = -40 \,^{\circ}\text{C} \text{ to } + 105 \,^{\circ}\text{C}/-40 \,^{\circ}\text{C} \text{ to } + 85 \,^{\circ}\text{C})$

					Value		11::4	Damaria.
Parameter	Symbol	Pin name	Condition	Min	Тур	Max	Unit	Remarks
	Vihs	Port pin	When CMOS hysteresis input type1 are selected	0.7 × Vcc	_	Vcc + 0.3	V	
	VIHC	Port pin	When CMOS hysteresis input type2 are selected	0.8 × Vcc	_	Vcc + 0.3	V	
"H" level input voltage	VIHA	Port pin	When Automotive inputs are selected	0.8 × Vcc	_	Vcc + 0.3	V	
	VIHT	Port pin	When TTL input levels are selected	2.0	_	Vcc + 0.3	V	
	V _{IH1}	MD2 to MD0	CMOS level input	0.7 × Vcc	_	Vcc + 0.3	V	
	V _{IH2}	MD3, INITX	CMOS hysteresis input	0.7 × Vcc	_	Vcc + 0.3	V	
	VILS	Port pin	When CMOS hysteresis input type1 are selected	Vss - 0.3	_	0.3 × Vcc	V	
	VILC	Port pin	When CMOS hysteresis input type2 are selected	Vss - 0.3	_	0.2 × Vcc	V	
"L" level	VILA	Port pin	When Automotive inputs are selected	Vss - 0.3	_	0.5 × Vcc	V	
input voltage	VILT	Port pin	When TTL input levels are selected	Vss - 0.3		0.8	V	
	VIL1	MD2 to MD0	CMOS level input	Vss - 0.3	_	0.3 × Vcc	V	
	V _{IL2}	MD3, INITX	CMOS hysteresis input	Vss - 0.3	_	0.3 × Vcc	V	
	V _{OH1}	Port pin	$V_{CC} = 5.0 \text{ V},$ $I_{OH} = -2.0 \text{ mA/}$ $V_{CC} = 3.3 \text{ V},$ $I_{OH} = -1.0 \text{ mA}$	Vcc - 0.5	_	_	V	*1
"H" level output voltage	V _{OH2}	I ² C common port pin	Vcc = 5.0 V, $IoH = -3.0 mA/$ $Vcc = 3.3 V,$ $IoH = -3.0 mA$	Vcc - 0.5	_	_	V	
	Vонз	Port pin	Vcc = 5.0 V, $IoH = -5.0 mA/$ $Vcc = 3.3 V,$ $IoH = -3.0 mA$	Vcc - 0.5	_	_	V	*1

 $(Vcc = 3.0 \text{ V to } 3.6 \text{ V/ } 4.5 \text{ V to } 5.5 \text{ V}, \text{ Vss} = \text{AVss} = 0 \text{ V}, \text{ T}_{A} = -40 \,^{\circ}\text{C} \text{ to } + 105 \,^{\circ}\text{C}/-40 \,^{\circ}\text{C} \text{ to } + 85 \,^{\circ}\text{C})$

Parameter	Sym-	Pin	Condition		Value		Unit	Remarks
i arameter	bol	name	Condition	Min	Тур	Max		Nemarks
"L" level output voltage	Vol1	Port pin	$V_{CC} = 5.0 \text{ V},$ $I_{OH} = -2.0 \text{ mA/}$ $V_{CC} = 3.3 \text{ V},$ $I_{OH} = -1.0 \text{ mA}$	_		0.4	٧	*1
	Vol2	I ² C com- mon port pin	$V_{CC} = 5.0 \text{ V},$ $I_{OH} = -3.0 \text{ mA/}$ $V_{CC} = 3.3 \text{ V},$ $I_{OH} = -3.0 \text{ mA}$	_	_	0.4	V	
	Volз	Port pin	$V_{CC} = 5.0 \text{ V},$ $I_{OH} = -5.0 \text{ mA/}$ $V_{CC} = 3.3 \text{ V},$ $I_{OH} = -3.0 \text{ mA}$	_	_	0.4	V	*1
Input leak current	lι∟	_	Vcc = AVcc = 5.0 V, Vss < Vı < Vcc	-5	_	+ 5	μΑ	
Pull-up resistance value	Rup	Port pin	_	25	50	100	kΩ	
Pull-down resistance value	Rdown	Port pin	_	25	50	100	kΩ	

(Continued)

 $(Vcc = 3.0 \text{ V to } 3.6 \text{ V} / 4.5 \text{ V to } 5.5 \text{ V}, \text{ Vss} = \text{AVss} = 0 \text{ V}, \text{ T}_{\text{A}} = -40 \,^{\circ}\text{C} \text{ to } + 105 \,^{\circ}\text{C} / -40 \,^{\circ}\text{C} \text{ to } + 85 \,^{\circ}\text{C})$

Parameter	Sym-	Pin	Condition		Value		Unit	Remarks
Parameter	bol	name	Condition	Min	Тур	Max	Onit	Remarks
	Іссз	VCC	Vcc = 3.3 V CPU core : 80 MHz,		75	102	mA	$T_A = -40$ °C to +105 °C
	Icc5	VCC	Vcc = 5.0 V CPU core : 80 MHz,		75	102	mA	$T_A = -40 ^{\circ}\text{C} \text{ to } +85 ^{\circ}\text{C}$
	Iccs3	VCC	Vcc = 3.3 V sleep mode		15	45	mA	
	Iccs ₅	VCC	Vcc = 5.0 V sleep mode		15	45	mA	
Power supply current	Істѕз	VCC	Vcc = 3.3 V stop mode (at using RTC) *3	_	100	550	μА	T _A = +25 °C When the CR oscillator is operating and low voltage detection is enabled.
	Істѕѕ	VCC	Vcc = 5.0 V stop mode (at using RTC) *3		200	650	μА	T _A = +25 °C When the CR oscillator is operating and low voltage detection is enabled.
	Ісснз	VCC	Vcc = 3.3 V stop mode (oscillation stop) *4		100	500	μΑ	T _A = +25 °C When the CR oscillator is stopping and low voltage detection is enabled.
	Ісснь	VCC	Vcc = 5.0 V stop mode (oscillation stop) *4	l	150	600	μΑ	T _A = +25 °C When the CR oscillator is stopping and low voltage detection is enabled.
	Iccf	VCC	Flash programming (Write/Erase)		25	50	mA	*2
Input capacitance	Сім	Except VCC, AVCC, VSS, AVSS	_	_	5	15	pF	

^{*1:} The drive power varies depending on the power supply voltage (3.3 V, 5.0 V).

^{*2:} The power supply current when writing or erasing by executing the automatic algorithm.

^{*3:} When the main clock oscillator is stopped and CR oscillator is operating (using the CR oscillator clock in the RTC) and the low voltage detection is enabled.

^{*4:} When the main clock oscillator is stopped, the CR oscillator is stopped and the low voltage detection is enabled.

4. AC characteristics

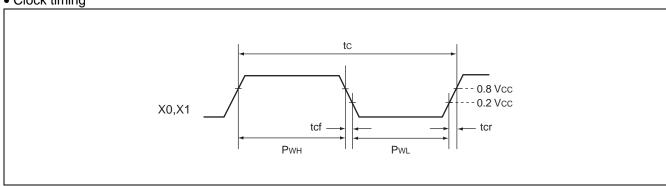
(1) Clock timing

 $(Vcc = 3.0 \text{ V to } 3.6 \text{ V} / 4.5 \text{ V to } 5.5 \text{ V}, \text{ Vss} = \text{AVss} = 0 \text{ V}, \text{ T}_{A} = -40 ^{\circ}\text{C} \text{ to } + 125 ^{\circ}\text{C} / -40 ^{\circ}\text{C} \text{ to } + 85 ^{\circ}\text{C})$

Parameter	Sym-	Pin	Con-		Value		Unit	Remarks
Farameter	bol	name	dition	Min	Тур	Max	Oilit	Remarks
Clock frequency	Fc	X0, X1		3.5	4	16	MHz	When using the oscillator circuit
	10	λ0, λ1		3.5	_	32	MHz	When using an external clock
Clock cycle time	t c	X0, X1		62.5	_	285.7	ns	When using the oscillator circuit
	ic	Λυ, Λ1		31.25	_	285.7	ns	When using an external clock
Internal operation clock frequency	Fcp	_	_	_	_	80	MHz	CPU clock, when using PLL*
lifequency	FCPP			_	_	40	MHz	Peripheral clock
Internal operation clock cycle time	t cp	_		12.5	_	_	ns	CPU clock, when using PLL
	tcpp			25	_	_	ns	Peripheral clock
Input clock pulse width	Pwh, Pwl	X0		30	_	_	ns	
Input clock rise/fall time	tcf, tcr	X0		_	_	5	ns	

^{*:} When using the clock modulator, set such that the maximum value of the modulated frequency is 96 MHz or less.

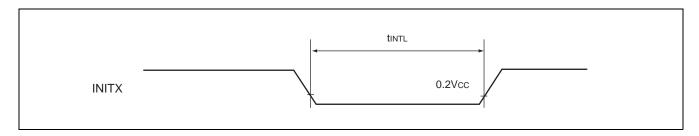




(2) Reset input

 $(Vcc = 3.0 \text{ V to } 3.6 \text{ V} / 4.5 \text{ V to } 5.5 \text{ V}, \text{ Vss} = \text{AVss} = 0 \text{ V}, \text{ T}_{A} = -40 \,^{\circ}\text{C} \text{ to } + 105 \,^{\circ}\text{C} / -40 \,^{\circ}\text{C} \text{ to } + 85 \,^{\circ}\text{C})$

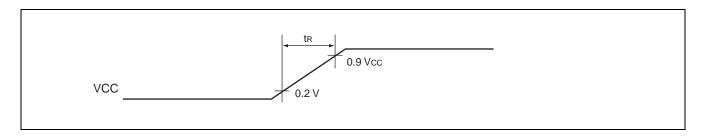
Parameter	Symbol	Pin name	Pin name Condition	Value	Unit	
Faranietei	Зуппоот	Fill Hallie	Condition	Min	Max	Oilit
INITX input time (at power-on or stop mode)	tur			Oscillation stabilization time of oscillator + 2.6	_	ms
INITX input time (other than the above)	tintl INITX —		20	_	μs	



(3) Specification for power-on

 $(Vcc = 3.0 \text{ V to } 3.6 \text{ V} / 4.5 \text{ V to } 5.5 \text{ V}, \text{ Vss} = \text{AVss} = 0 \text{ V}, \text{ T}_{A} = -40 ^{\circ}\text{C} \text{ to } + 105 ^{\circ}\text{C} / -40 ^{\circ}\text{C} \text{ to } + 85 ^{\circ}\text{C})$

Parameter	Symbol	Pin name	Condition	Valu	Unit	
	Symbol	Fin name	Condition	Min	Max	Offic
Power supply rising time	t R	VCC	_	0.1	100	ms
Power supply start time	_	_	_	0.2		V
Power supply end time		_	_	_	0.9 × Vcc	V



(4) LIN-USART timing

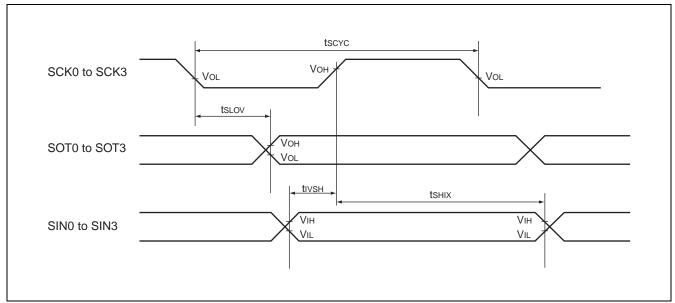
 $(Vcc = 3.0 \text{ V to } 3.6 \text{ V} / 4.5 \text{ V to } 5.5 \text{ V}, \text{ Vss} = \text{AVss} = 0 \text{ V}, \text{ T}_{A} = -40 ^{\circ}\text{C} \text{ to } + 105 ^{\circ}\text{C} / -40 ^{\circ}\text{C} \text{ to } + 85 ^{\circ}\text{C})$

Parameter	Symbol	Pin name	Condition	Va	lue	Unit
Parameter	Syllibol	Pili liaille	Condition	Min	Max	Onne
Serial clock cycle time	t scyc	SCK0 to SCK3		8 × tclkp	_	ns
$SCK \downarrow \to SOT$ delay time	tsLOV	SCK0 to SCK3, SOT0 to SOT3	Internal shift	- 80	+ 80	ns
Valid SIN → SCK ↑	t ıvsh	SCK0 to SCK3, SIN0 to SIN3	clock mode	100	_	ns
$SCK \uparrow \rightarrow valid SIN hold time$	t shix	SCK0 to SCK3, SIN0 to SIN3		60	_	ns
Serial clock "H" pulse width	t shsl	SCK0 to SCK3		$4 \times t$ CLKP		ns
Serial clock "L" pulse width	t slsh	SCK0 to SCK3		$4 \times t$ CLKP		ns
$SCK \downarrow \to SOT$ delay time	tsLOV	SCK0 to SCK3, SOT0 to SOT3	External shift	_	150	ns
Valid SIN → SCK ↑	t ıvsh	SCK0 to SCK3, SIN0 to SIN3	clock mode	60		ns
$SCK \uparrow \rightarrow Valid SIN hold time$	t sнıx	SCK0 to SCK3, SIN0 to SIN3		60	_	ns

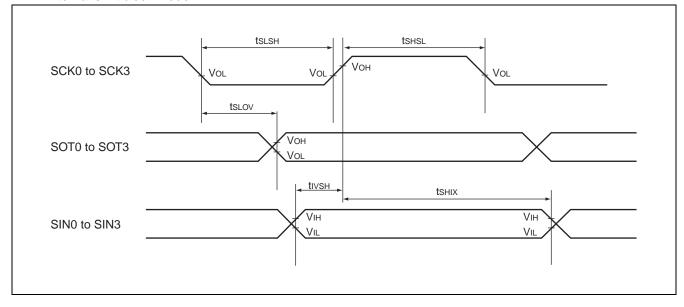
Notes: • Above values are AC characteristics for CLK synchronous mode.

• tclkp is the cycle time of the peripheral clock.

• Internal shift clock mode



• External shift clock mode

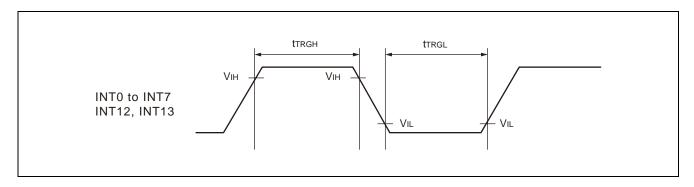


(5) Trigger input timing

 $(Vcc = 3.0 \text{ V to } 3.6 \text{ V} / 4.5 \text{ V to } 5.5 \text{ V}, \text{ Vss} = \text{AVss} = 0 \text{ V}, \text{ T}_{A} = -40 ^{\circ}\text{C} \text{ to } + 105 ^{\circ}\text{C} / -40 ^{\circ}\text{C} \text{ to } + 85 ^{\circ}\text{C})$

Parameter	Symbol	Pin name	Va	Unit	
	Syllibol	riii iiaiiie	Min	Max	Oilit
External interrupt input pulse width	t trgh t trgl	INT0 to INT7 INT12, INT13	4 × tclkp	_	ns

Note: tclkp is the cycle time of the peripheral clock.

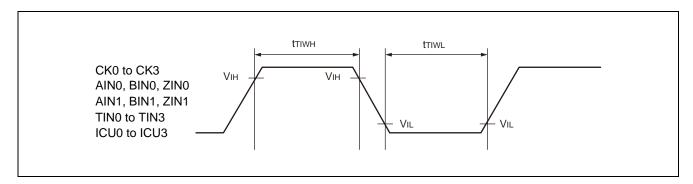


(6) Timer related resource input timing

 $(Vcc = 3.0 \text{ V to } 3.6 \text{ V} / 4.5 \text{ V to } 5.5 \text{ V}, \text{ Vss} = \text{AVss} = 0 \text{ V}, \text{ T}_{A} = -40 ^{\circ}\text{C} \text{ to } + 105 ^{\circ}\text{C} / -40 ^{\circ}\text{C} \text{ to } + 85 ^{\circ}\text{C})$

Parameter	Symbol	Pin name	Va	Unit	
raiailletei	Symbol Fill flame		Min	Max	Offic
Free-run timer input clock pulse width		CK0 to CK3	4 × tclkp	_	ns
Up/down counter input pulse width	Ise width triwh triwL AINO, AIN BINO, BINO, ZINO, ZINO, ZIN		4 × tclkp	_	ns
Reload timer input pulse width		TIN0 to TIN3	4 × tclkp		ns
Input capture input pulse width		ICU0 to ICU3	4 × tclkp	_	ns

Note: tolkp is the cycle time of the peripheral clock.



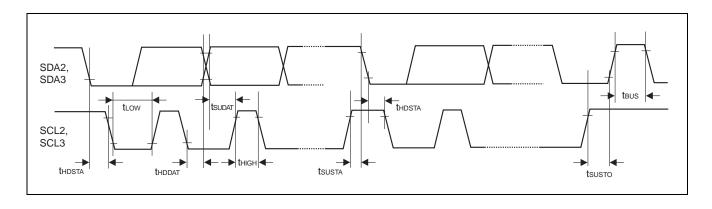
(7) I2C timing

 $(Vcc = 3.0 \text{ V to } 3.6 \text{ V} / 4.5 \text{ V to } 5.5 \text{ V}, \text{ Vss} = \text{AVss} = 0 \text{ V}, \text{ T}_{A} = -40 ^{\circ}\text{C} \text{ to } + 105 ^{\circ}\text{C} / -40 ^{\circ}\text{C} \text{ to } + 85 ^{\circ}\text{C})$

Parameter	Symbol	Pin name	Condition	Standard Mode		Fast Mode *1		Unit	
Farameter	Symbol	Fill Hallie	Condition	Min	Max	Min	Max	Offic	
SCL clock frequency	fscL		$R = 1 k\Omega$	0	100	0	400	kHz	
"L" width of the SCL clock	t Low			4.7	_	1.3	_	μs	
"H" width of the SCL clock	t HIGH			4.0	_	0.6	_	μs	
Bus free time between STOP and START conditions	t BUS			4.7	_	1.3	_	μs	
SCL ↑→ SDA output delay time	t dldat	SDA2, SDA3, SCL2, SCL3		_	5× tclkp	_	5× tclkp	ns	
Setup time for a repeated START condition SCL ↑→ SDA ↓	t susta			4.7	_	0.6	_	μs	
Hold time for a repeated START condition SDA $\downarrow \rightarrow$ SCL \downarrow	t hdsta		SCL3		4.0		0.6	_	μs
Setup time for STOP condition SCL $\uparrow \rightarrow$ SDA \uparrow	t susto			4.0		0.6	_	μs	
SDA data input hold time SCL $\downarrow \rightarrow$ SDA $\downarrow \uparrow$	t hddat			2 × tclkp		2× tclkp	_	μs	
SDA data input setup time SDA $\downarrow \uparrow \rightarrow$ SCL \uparrow	t sudat			250	_	100	_	ns	

^{*1 :} For use at over 100 kHz, set the peripheral clock to at least 6 MHz.

Note: tclkp is the cycle time of the peripheral clock.



^{*2:} R and C are the pull-up resistance and load capacitance of the SCL and SDA lines.

5. Electrical characteristics for A/D converter

(Vcc = 3.0 V to 3.6 V/ 4.5 V to 5.5 V, Vss = AVss = 0 V, T_A = -40 °C to + 105 °C/-40 °C to + 85 °C)

Parameter	Symbol	Pin name		Value	Unit	Remarks	
Parameter	Syllibol	riii name	Min Typ		Max		Oilit
Resolution	_	_		_	10	bit	
Total error*1	_	_	_	_	± 3	LSB	
Linearity error*1	_	_	_	_	± 2.5	LSB	
Differential linearity error*1		_			± 1.9	LSB	
Zero transition voltage*1	Vот	AN0 to AN7	AVss- 1.5 LSB	AVss- 0.5 LSB	AVss- 2.5 LSB	V	
Full scale transition voltage*1	V _{FST}	AN0 to AN7	AVRH- 3.5 LSB	AVRH- 1.5 LSB	AVRH- 0.5 LSB	V	
Conversion time			1 *2	_	_	μs	Using at 5 V
Conversion time	_	_	3 *2	_	_	μs	Using at 3.3 V
Analog port input current	lain	AN0 to AN7	_	_	10	μΑ	
Analog input voltage	Vain	AN0 to AN7	AVss	_	AVRH	V	
Reference voltage	_	AVRH	AVss	_	AVcc	V	
Analog power supply current (analog + digital)	la	AVCC	_	2.4	4.7	mA	Including reference supply
Reference voltage supply current	lR	AVRH		0.65	1.0	mA	
Analog input equivalent capacitance	Cin	AN0 to AN7	_	_	8.5	pF	
Analog input equivalent	Rin	AN0 to AN7	_	_	2.6	kΩ	AVcc ≥ 4.5 V
resistance	IXIII	AND ID ANT			12.1	kΩ	AVcc ≥ 3.0 V
Output impedance of analog signal source	Rext	_	_	_	4.2	kΩ	

^{*1 :} Measured in the CPU sleep state

^{*2 :} Set no shorter than this time period in the peripheral clock and conversion setting register.

Notes on the A/D Converter

The diagram below shows the equivalent circuit of the sampling circuit in the A/D converter.

Apply the output impedance in the external circuit for the analog output under the following conditions.

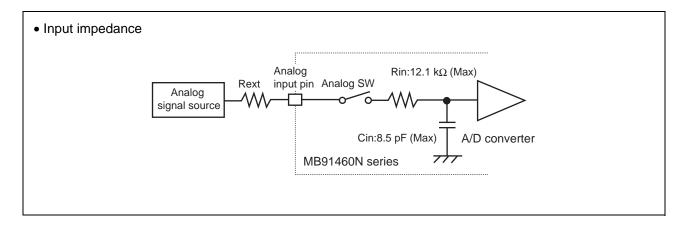
- The recommended output impedance for the external circuit is 4.2 k Ω or less.
- If an external capacitor is used, remember to consider the capacitive voltage divider effect due to the external capacitor and the internal capacitor in the chip. Accordingly, an external capacitance several thousand times that of the internal capacitance is recommended.
- The analog voltage sampling period may be too short if the output impedance of the external circuit is high. In this case, select Rext and Tsamp to satisfy the following condition.

Rext = Tsamp/ $(7 \times Cin)$ - Rin

Rext : Output impedance of the analog signal source

Tsamp : Sampling time

Cin : Equivalent capacitance of analog input Rin : Equivalent resistance of analog input



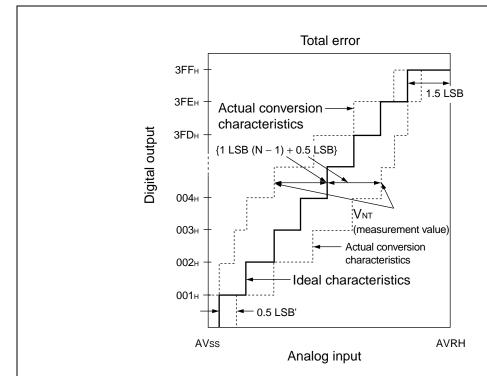
Definition of A/D converter terms

- Resolution
 - Analog variation that is recognizable by an A/D converter.
- · Linearity error

Deviation between actual conversion characteristics and a straight line connecting zero transition point (00 0000 0000 \leftrightarrow 00 0000 0001) and full scale transition point (11 1111 1110 \leftrightarrow 11 1111 1111).

- · Differential linearity error
 - Deviation of input voltage, which is required for changing output code by 1 LSB, from an ideal value.
- Total error

This error indicates the difference between actual and theoretical values, including the zero transition error/full scale transition error/linearity error.



1LSB' (ideal value) =
$$\frac{AVRH - AV_{SS}}{1024}$$
 [V]

Total error of digital output N =
$$\frac{V_{NT} - \{1 \text{ LSB'} \times (N-1) + 0.5 \text{ LSB'}\}}{1 \text{ LSB'}}$$

N : A/D converter digital output value

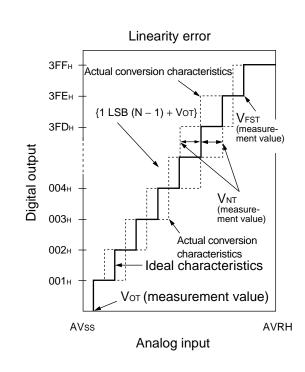
Vor' (ideal value) = AVss + 0.5 LSB' [V]

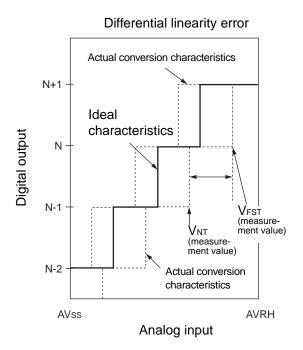
V_{FST}' (ideal value) = AVRH - 1.5 LSB' [V]

 V_{NT} : A voltage at which digital output transits from (N + 1) to N

(Continued)

(Continued)





Linearity error of digital output N = $\frac{V_{NT} - \{1LSB \times (N-1) + V_{OT}\}}{1LSB}$ [LSB]

Differential linearity error of digital output N = $\frac{V(N+1)T - VNT}{1LSB}$ [LSB]

$$1LSB = \frac{V_{FST} - V_{OT}}{1022} [V]$$

N : A/D converter digital output value

 V_{OT} : A voltage at which digital output transits from 000H to 001H. V_{FST} : A voltage at which digital output transits from 3FEH to 3FFH.

• Flash Memory Program/Erase Characteristics

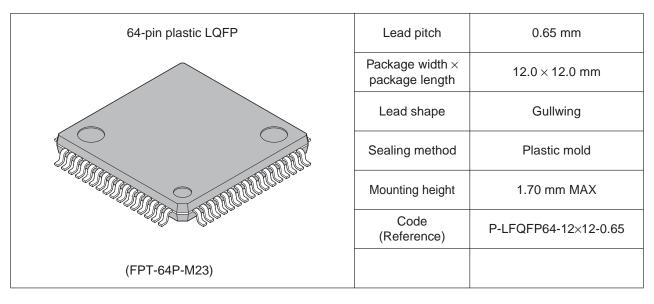
Parameter	Conditions	Value			Unit	Remarks	
Parameter	Conditions	Min	Тур	Max	Ollit	Nemarks	
Sector erase time		_	0.9	3.6	s	Excludes programming prior to erasure	
Chip erase time	$T_A = +25 ^{\circ}\text{C}$ $V_{CC} = 5.0 ^{\circ}\text{V}$		9	_	s	Excludes programming prior to erasure	
Word (16-bit width) programming time			23	370	μs	Except for the overhead time of the system level	
Program/Erase cycle	_	10000	_	_	cycle		
Flash memory data retention time	Average T _A = +85 °C	20	_	_	year	*	

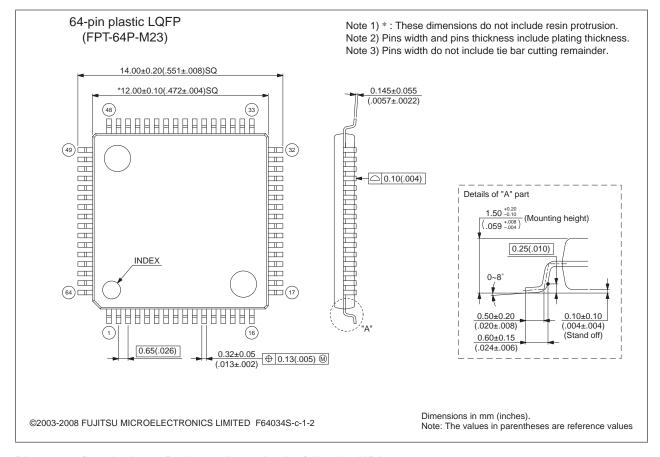
 $^{^*}$: The value is translated high-temperature measurement results of the technology reliability evaluation into average value at + 85 °C.

■ ORDERING INFORMATION

Part number	Package	Remarks
MB91F463NCPMC-GSE1	64-pin plastic LQFP (FPT-64P-M23)	Lead-free package

■ PACKAGE DIMENSION





Please confirm the latest Package dimension by following URL. http://edevice.fujitsu.com/package/en-search/

■ MAIN CHANGES IN THIS EDITION

Page	Section	Change Results
_	_	Changed the part number. MB91F463NB → MB91F463NC
13	■ I/O CIRCUIT TYPE Type J	Corrected "invertor for clock input (Xout)" to "hysteresis type".
37	■ MEMORY SPACE	Added the sector configuration for MB91F463NC in "3. flash memory sector configuration".
81	■ ORDERING INFORMATION	Changed the part number. MB91F463NBPMC → MB91F463NCPMC-GSE1

The vertical lines marked in the left side of the page show the changes.

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